

BACK-SIDE ILLUMINATED SIPM PROTOTYPES: FIRST CHARACTERISATION

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on behalf of the IBIS_NEXT Bologna group

INNOVATIVE BACKSIDE ILLUMINATED SiPM

Or just IBIS

An innovative concept of SiPM illuminated from back

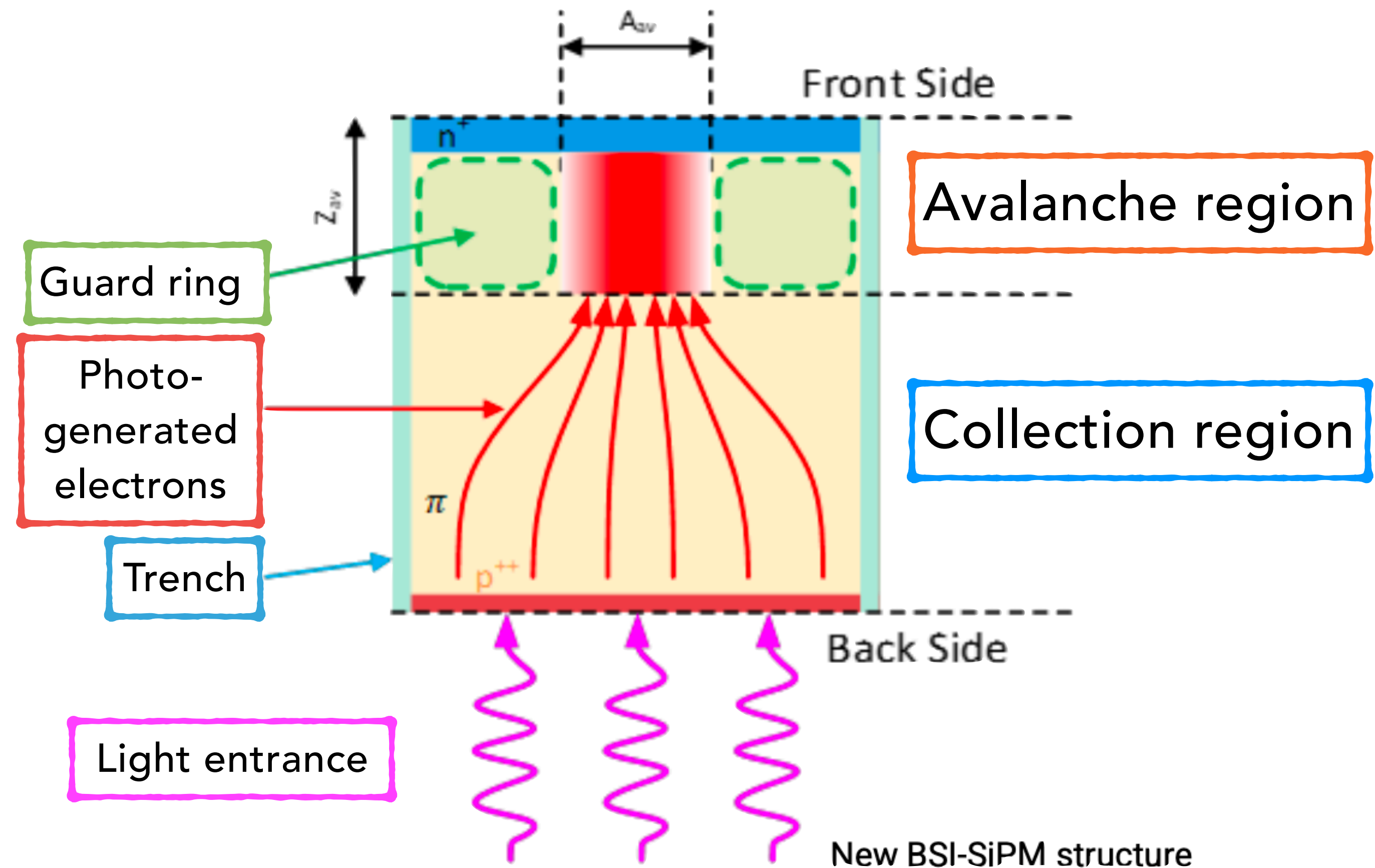
Advantages:

Up to 100% Fill Factor even w/ small cell pitch ($\approx 15\mu\text{m}$)

Low gain and external crosstalk

Increased radiation hardness due to smaller sensitive area

Easy to integrate with readout electronics



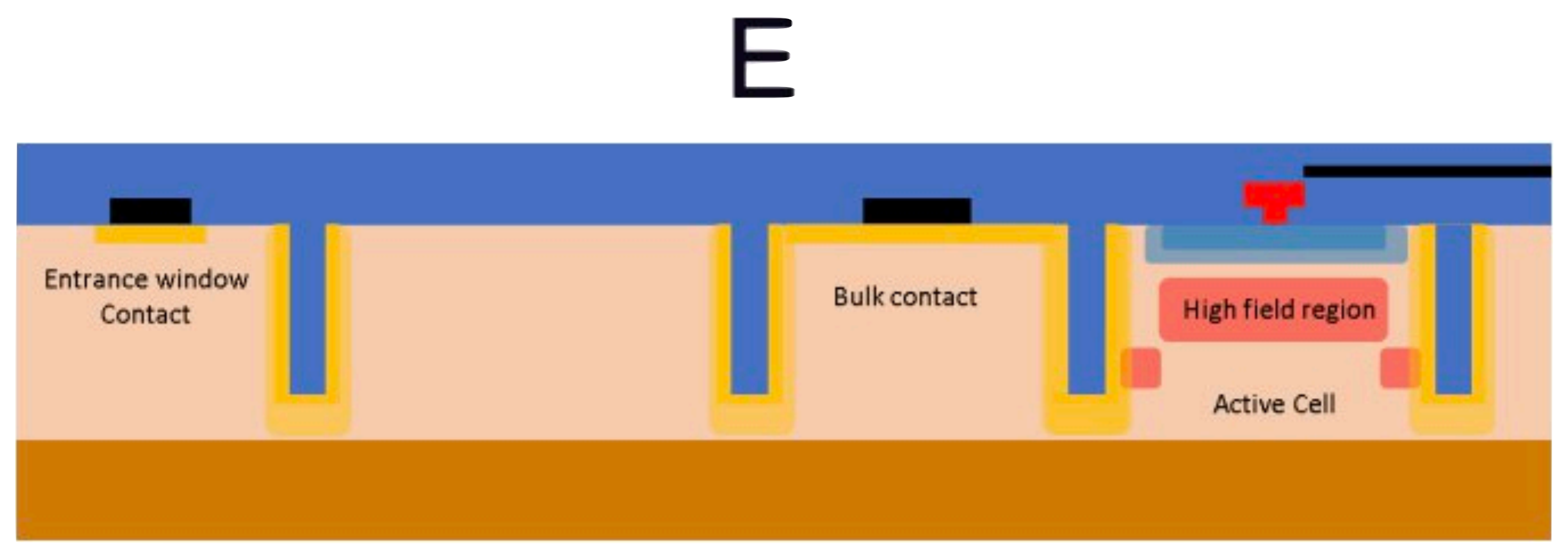
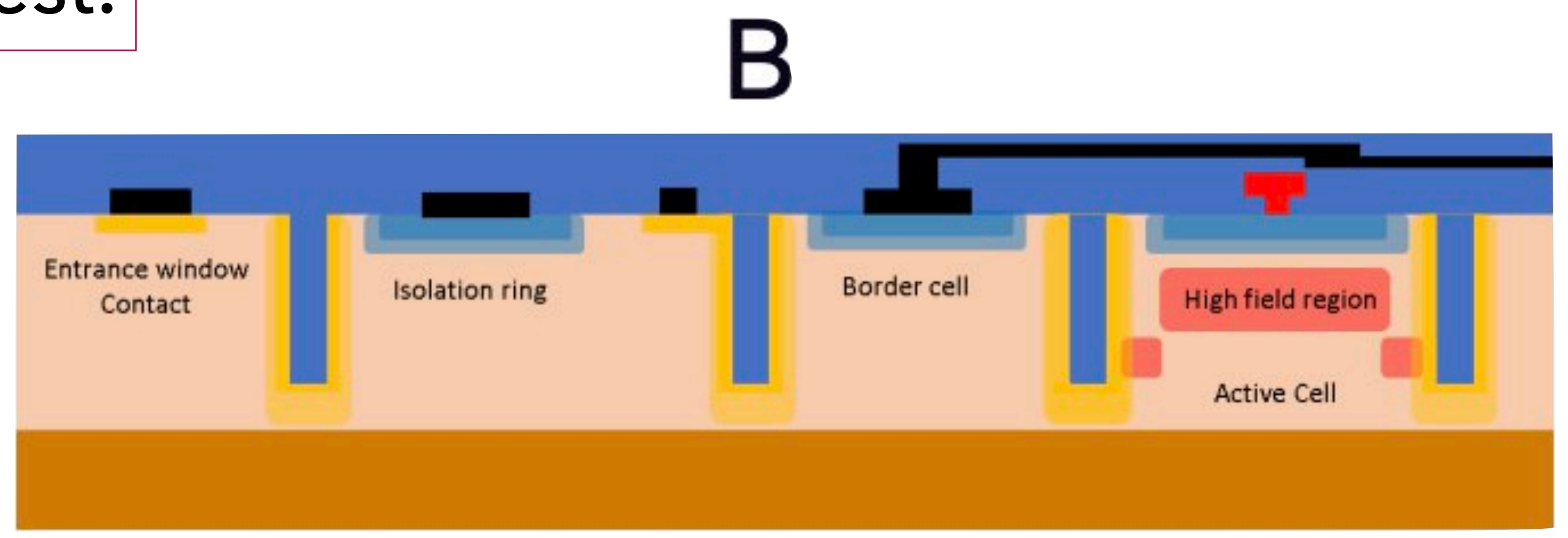
BACKSIDE ILLUMINATED SIPM IN BOLOGNA

We received two boards from FBK to test:

- Each board has:
- 2 split B SiPM
 - 2 split E SiPM

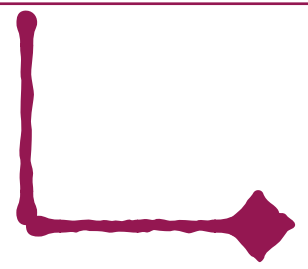
Differences among boards regard trench

PCB	Epitaxial thickness	Trench	1st Split	2nd Split	3rd Split	4th Split
1	Thin	Medium +	B	\\	E	E
2	Thin	Medium -	B	B	E	E

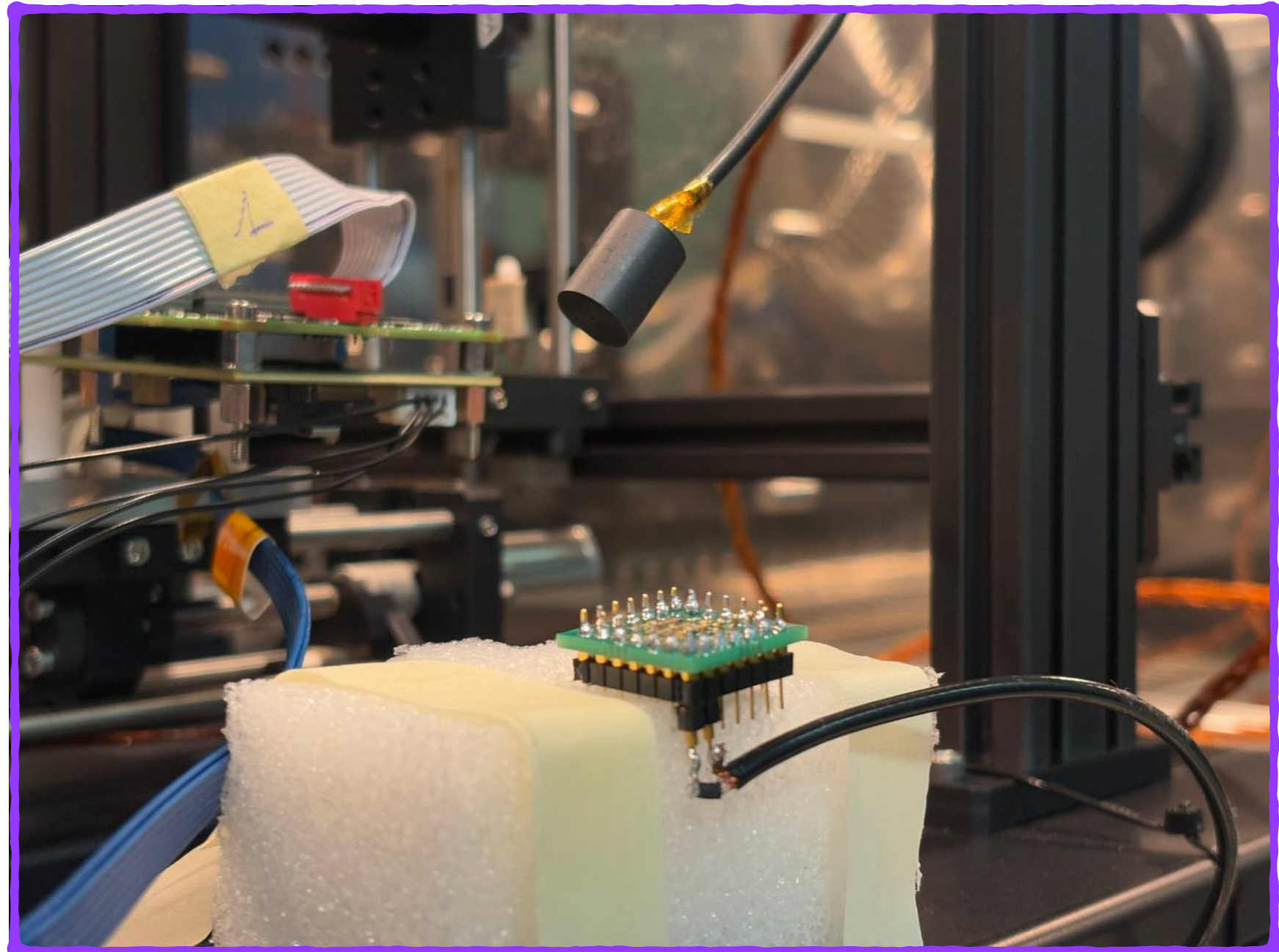
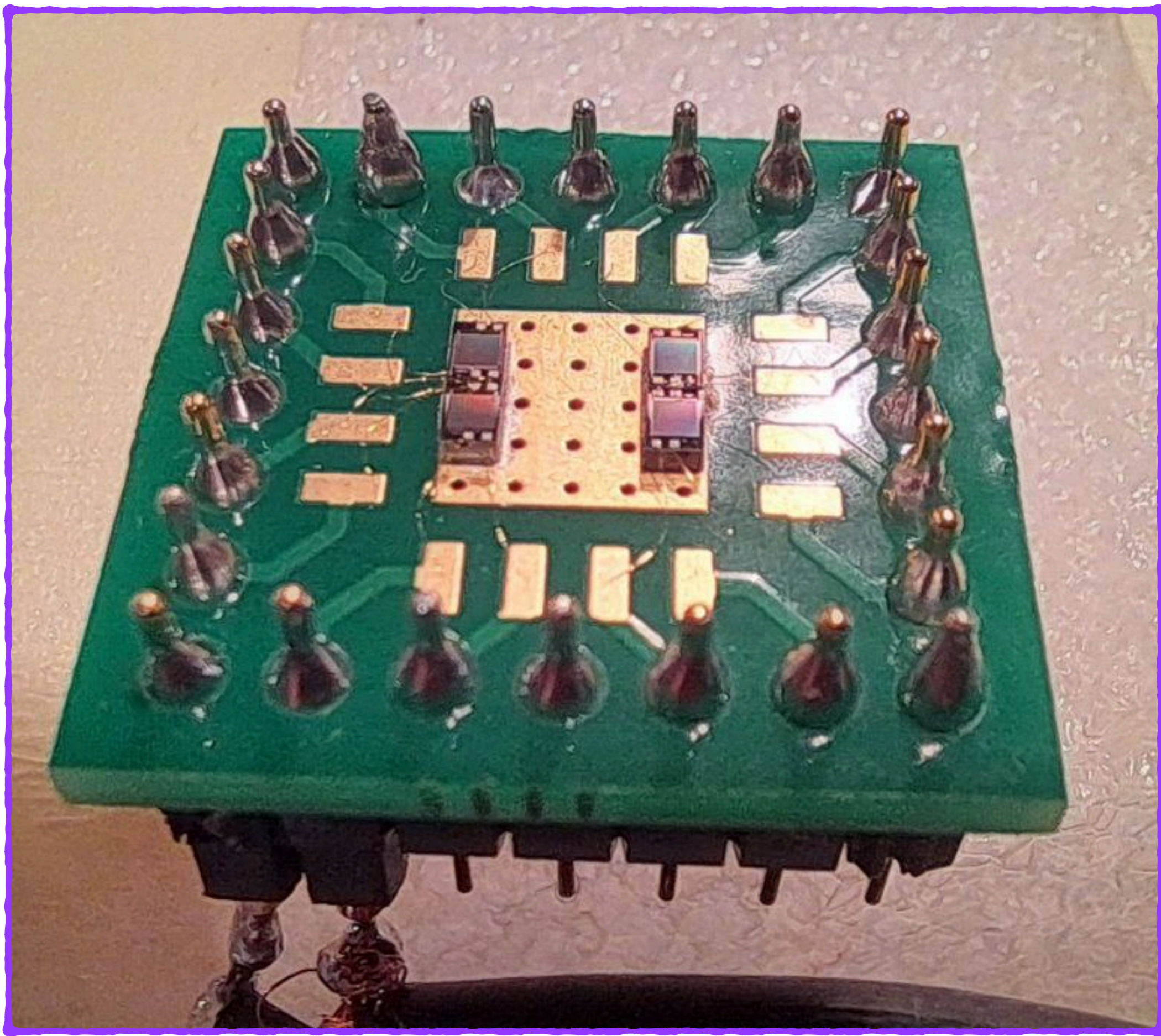
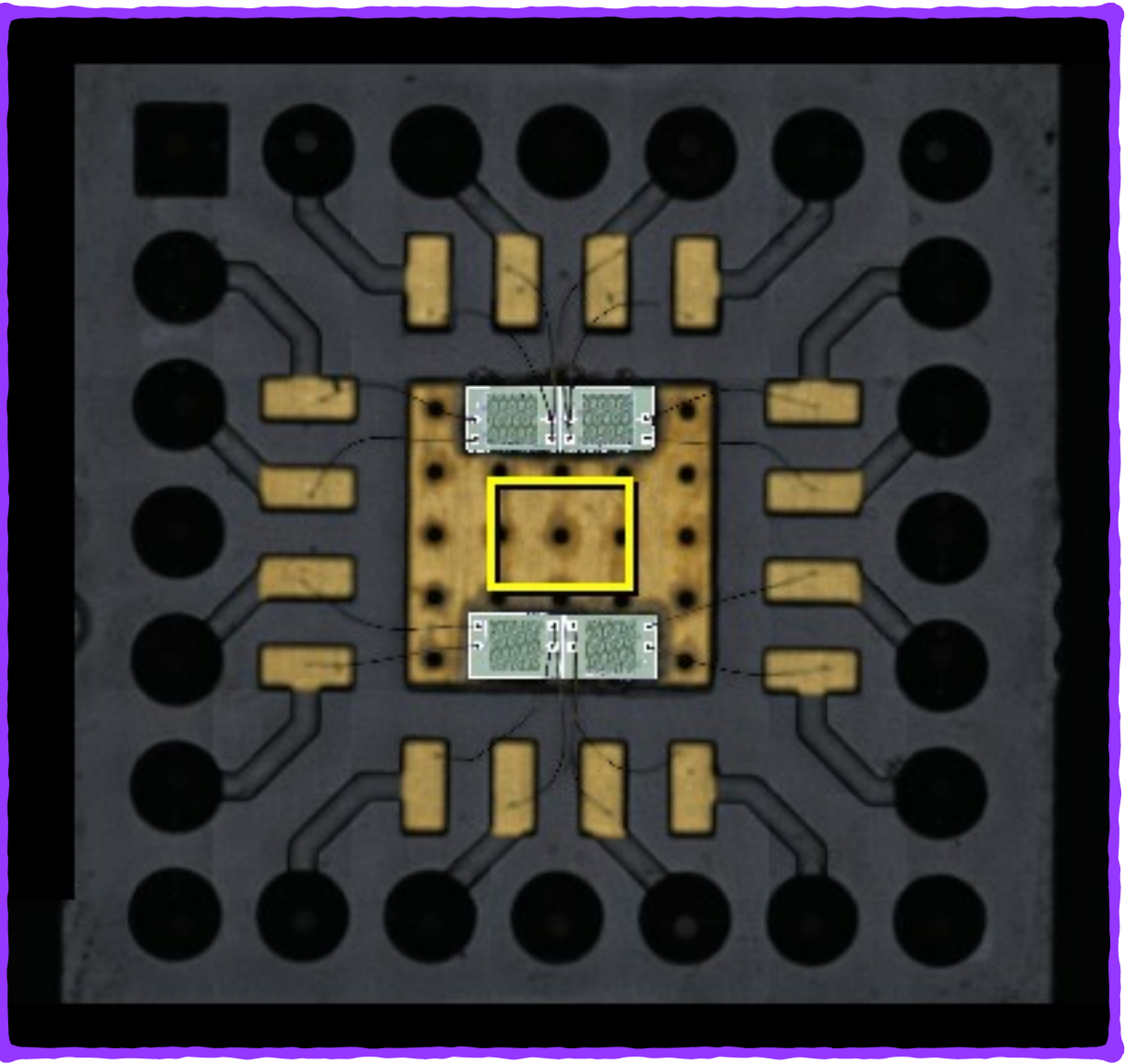
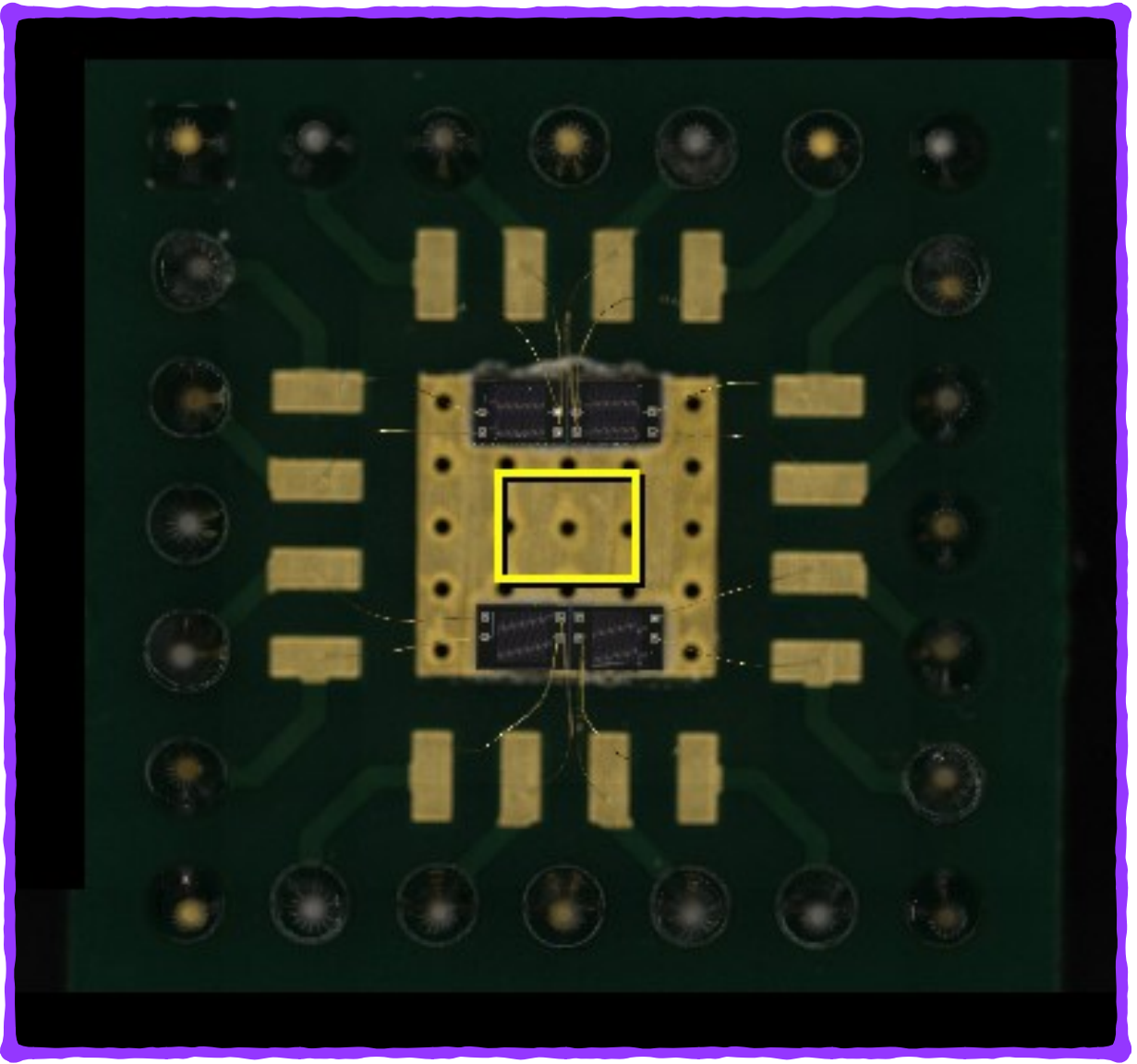


RESULTS FROM BOLOGNA

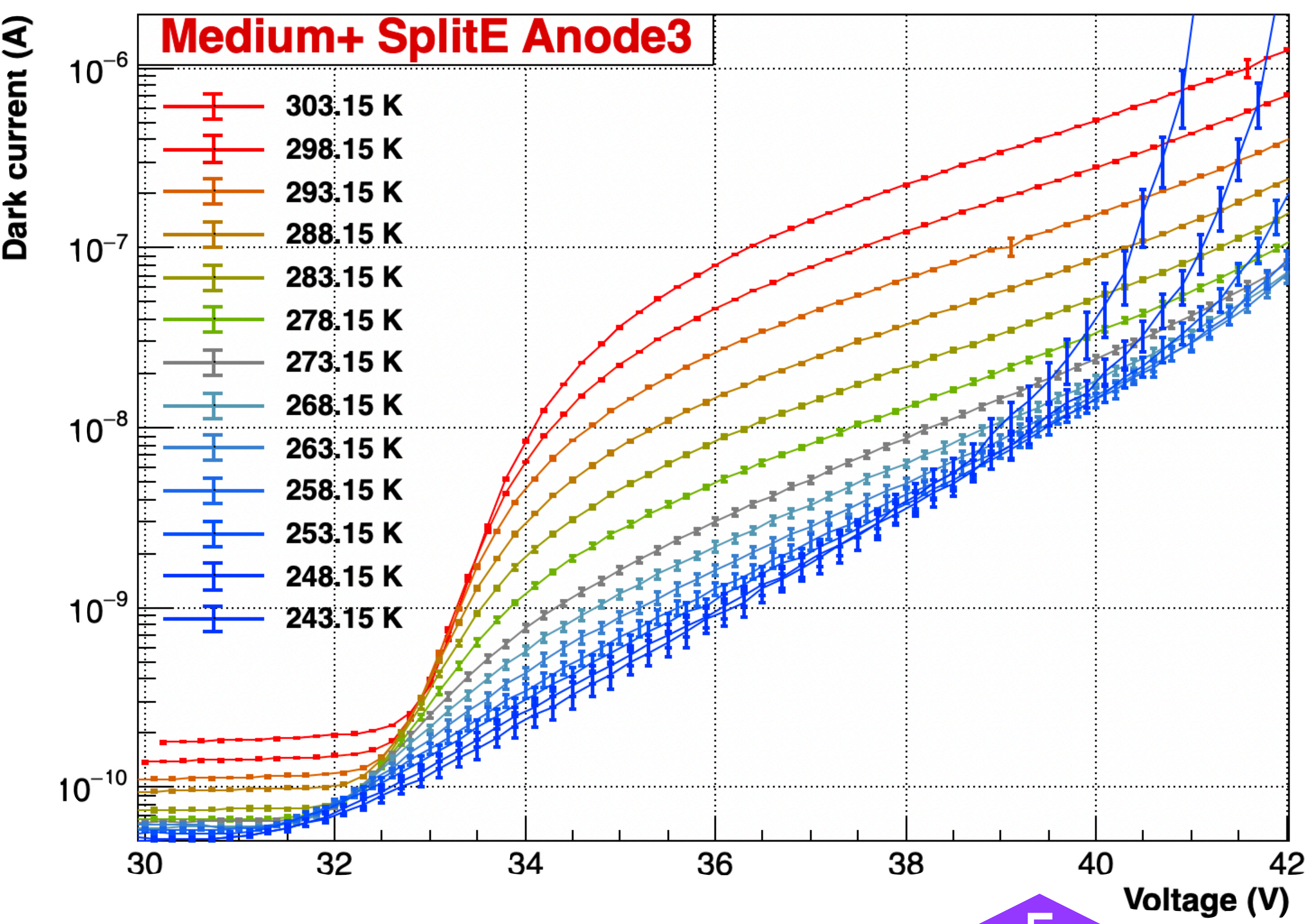
What we do?



IV-characterization in climatic chamber and now w/ LED



DARK CURRENT CHARACTERIZATION

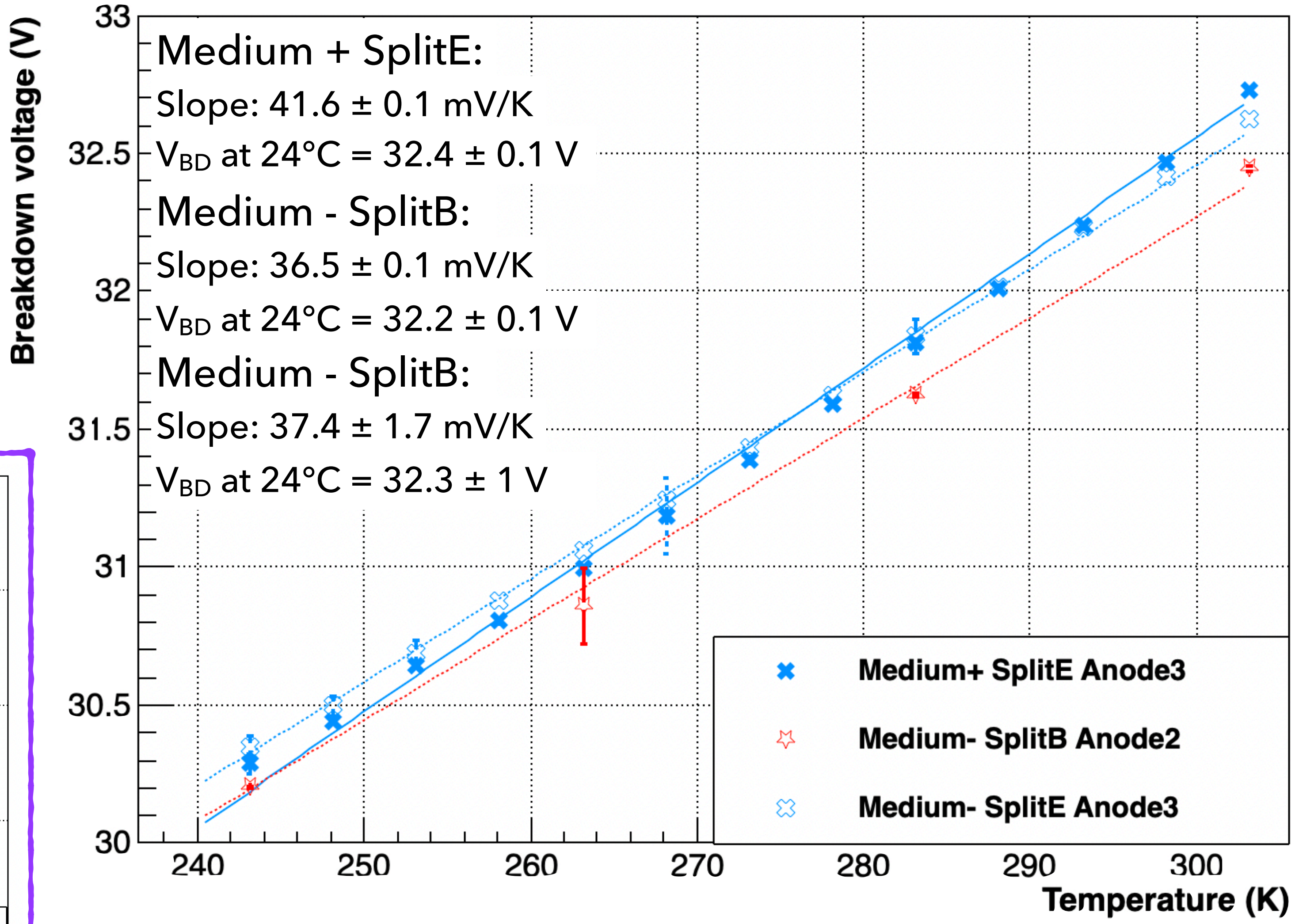
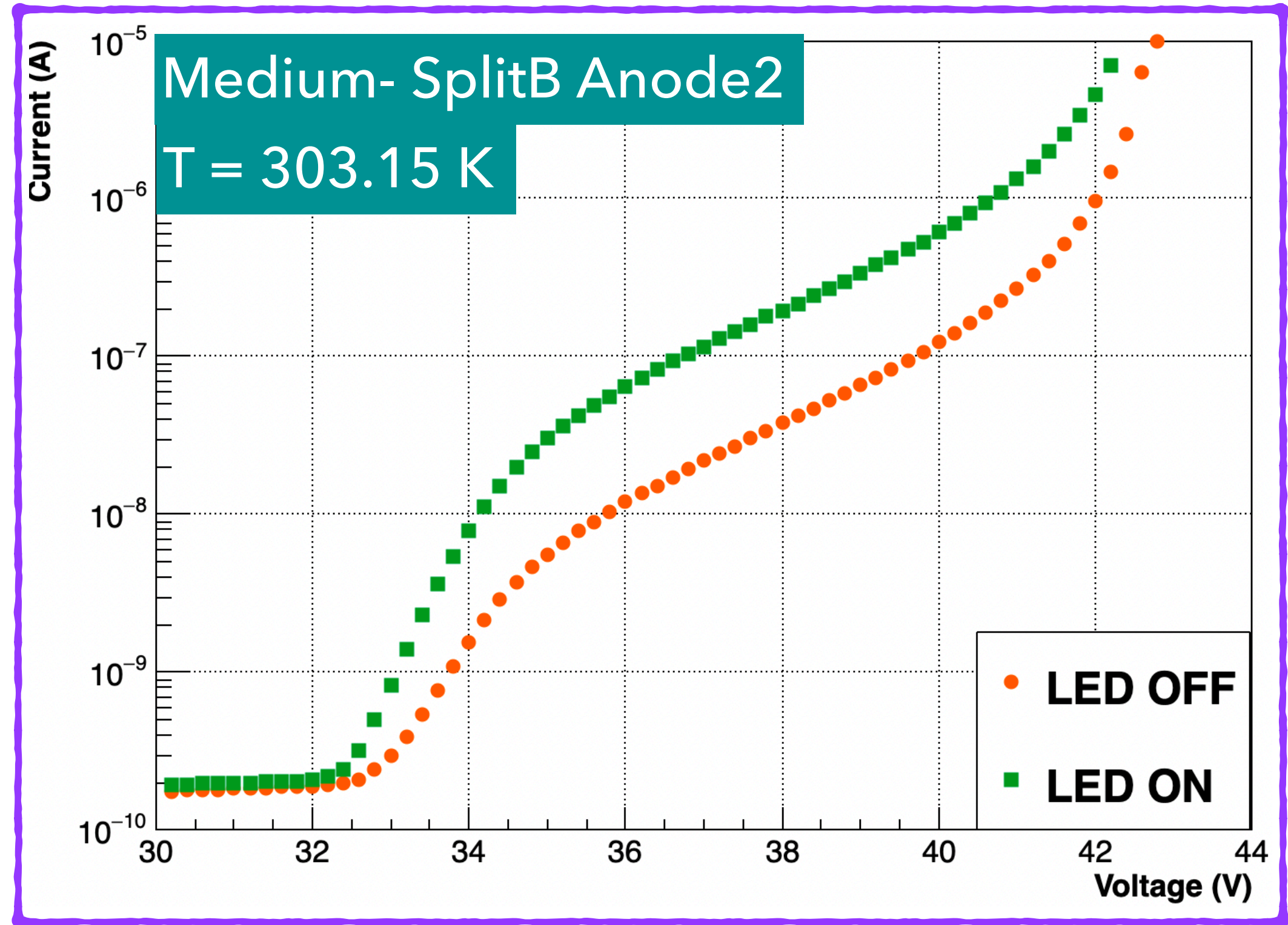


- Dark current studies:
- Range from 30 to -30 °C
 - Step of 5°C
 - Reverse and Forward scan
 - Extracting dark V_{BD}
 - Extracting $R_{quenching}$
 - Making a comparison among sensors

CALCULATING BREAKDOWN

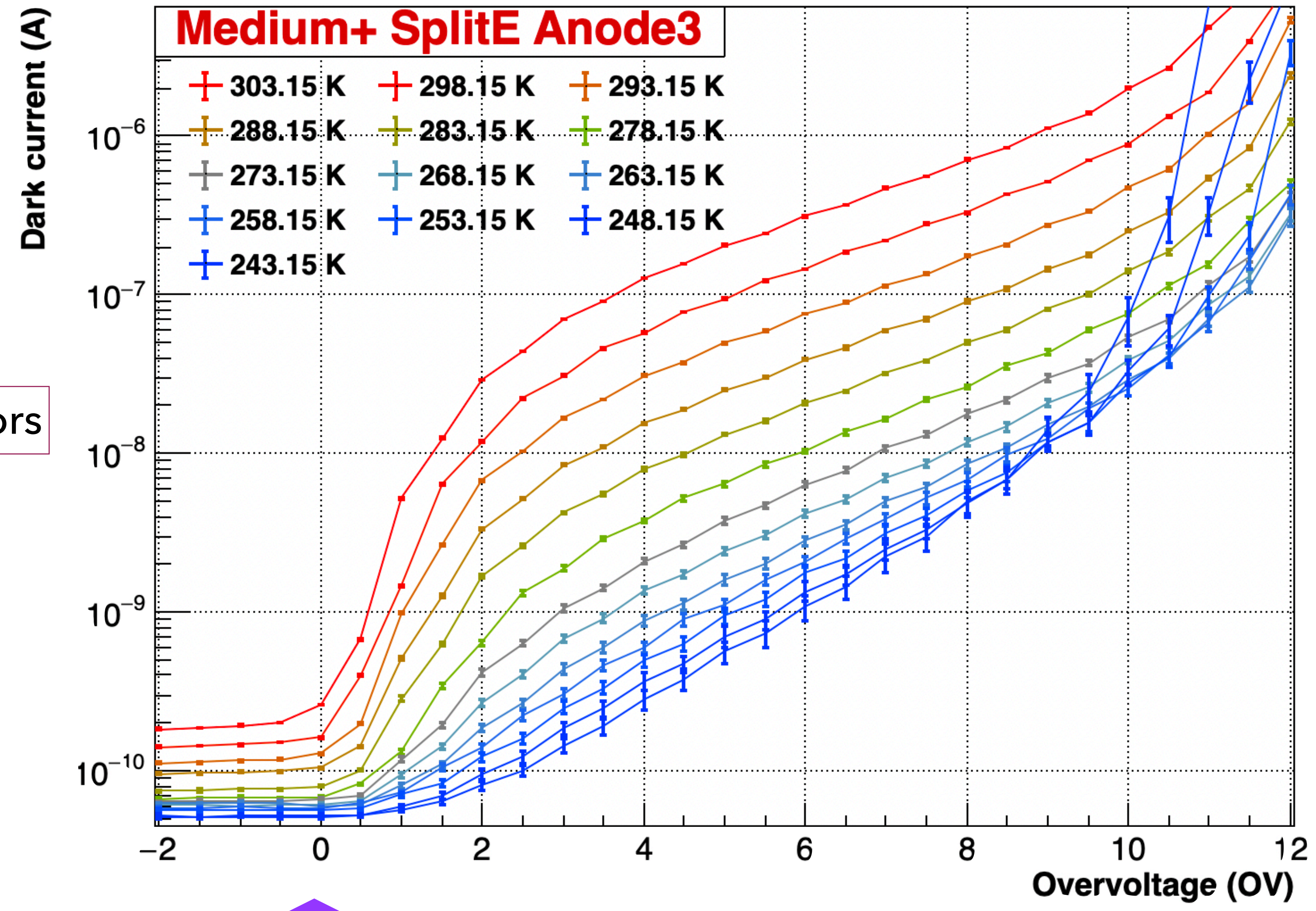
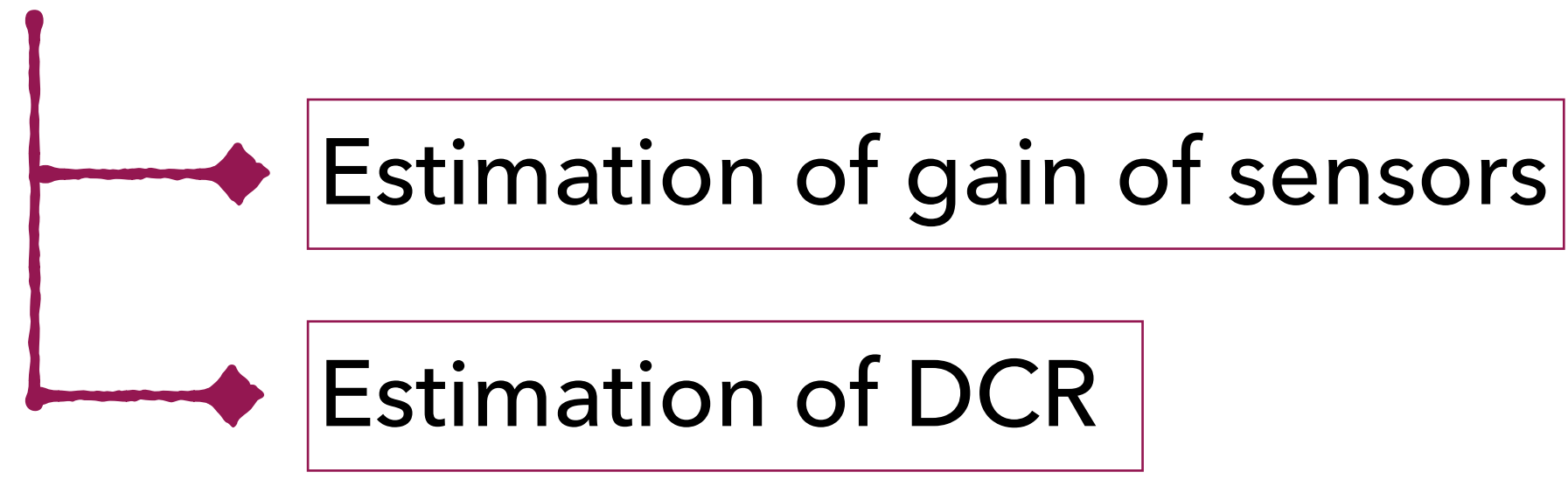
Test with yellow LED:

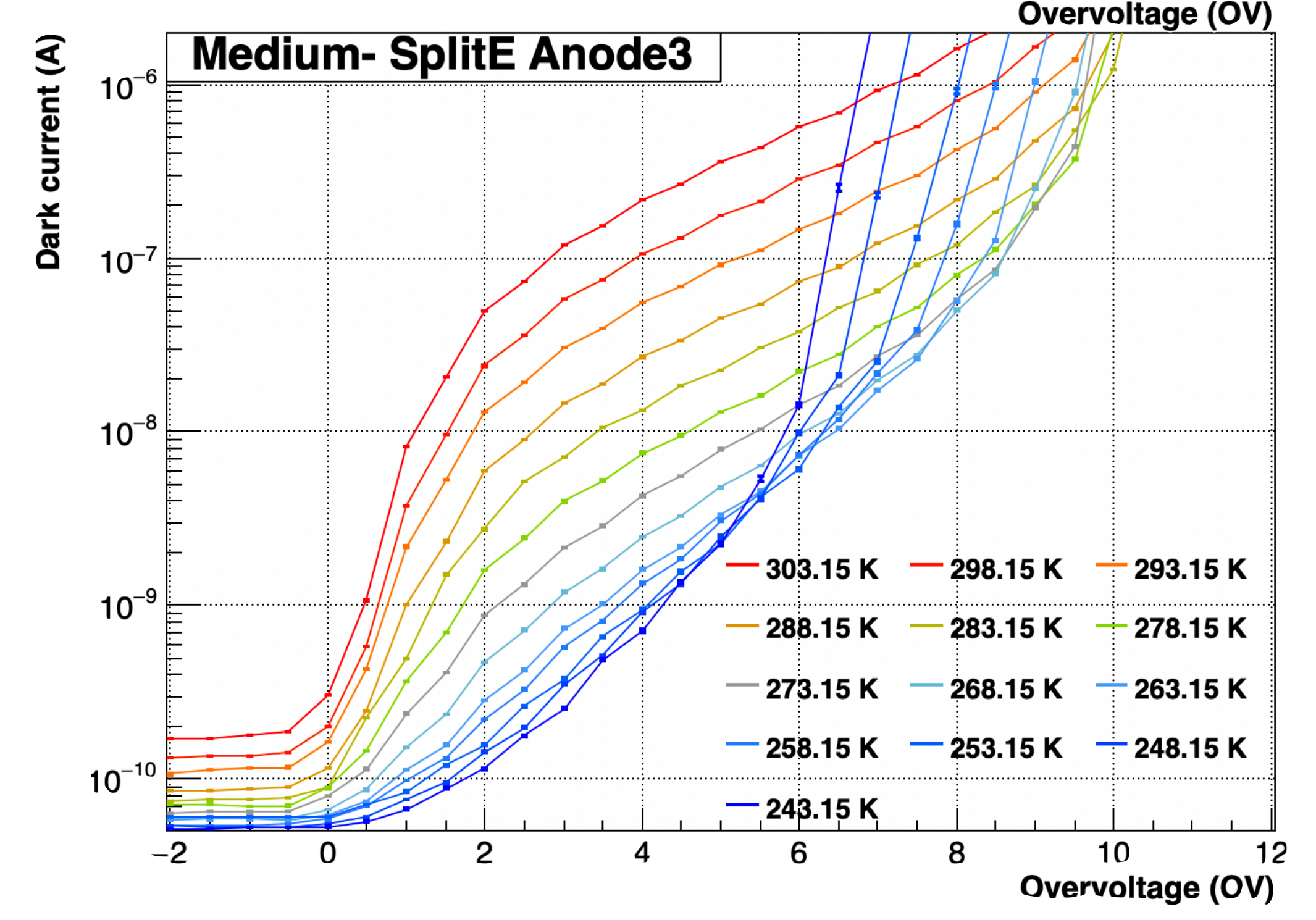
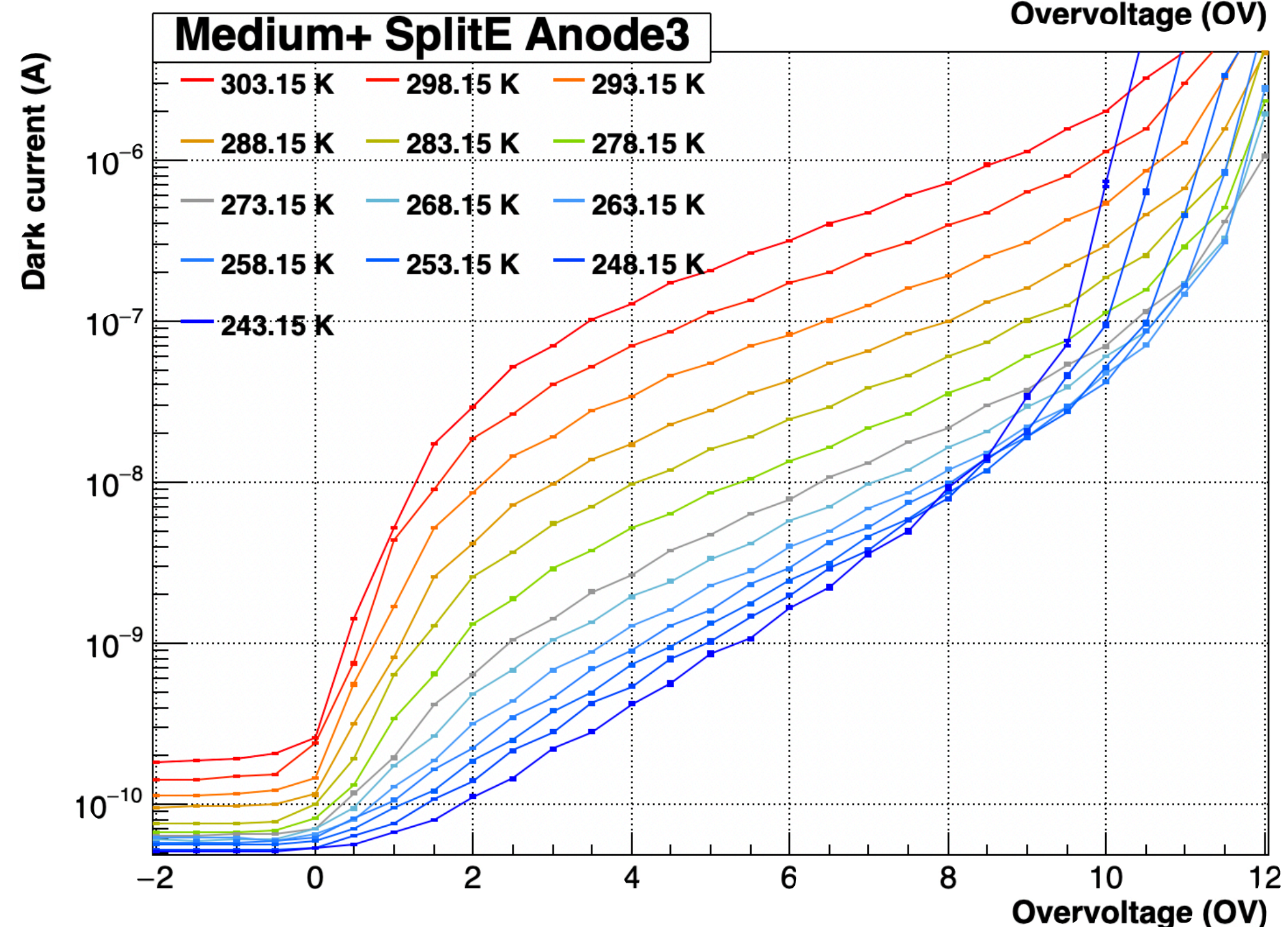
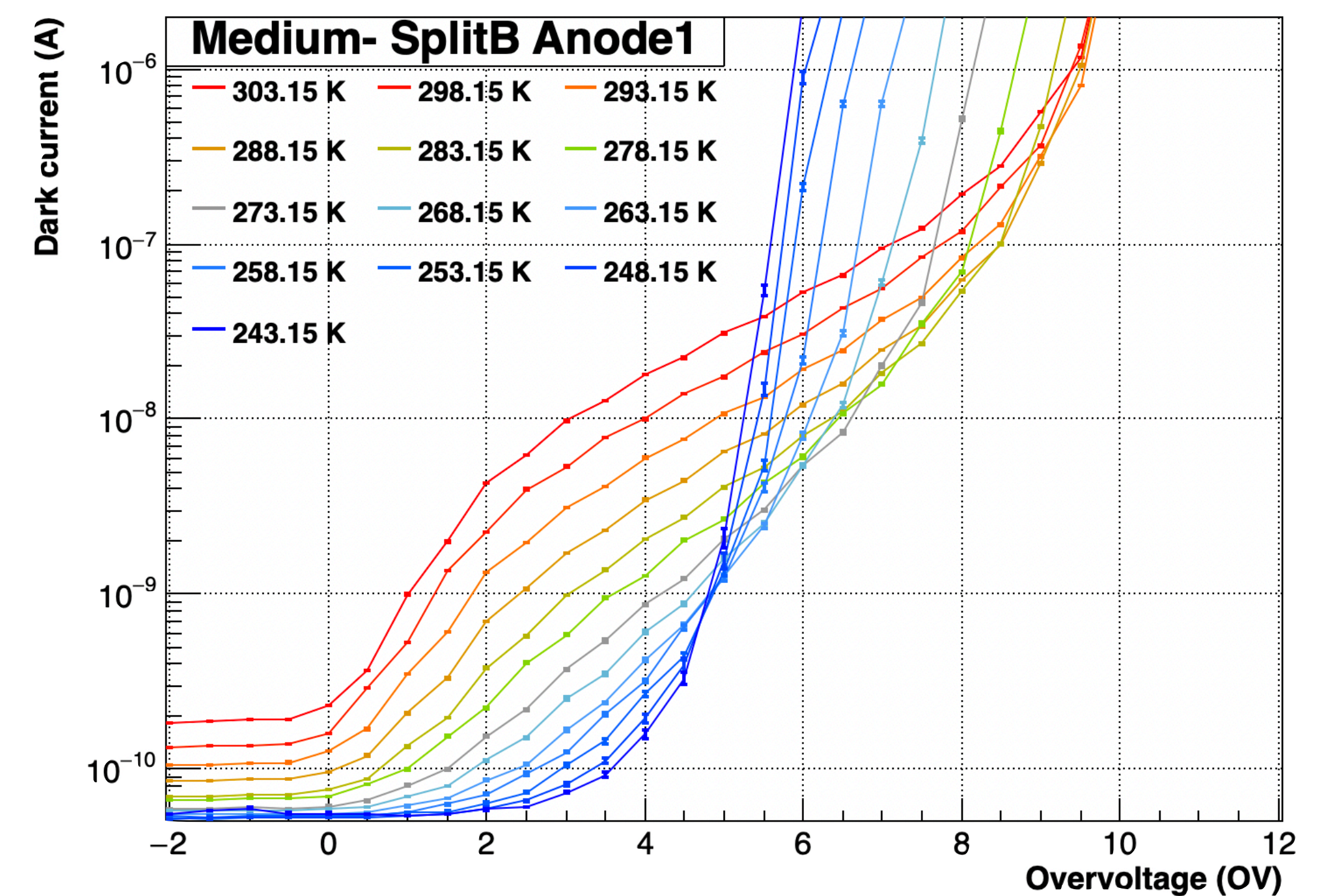
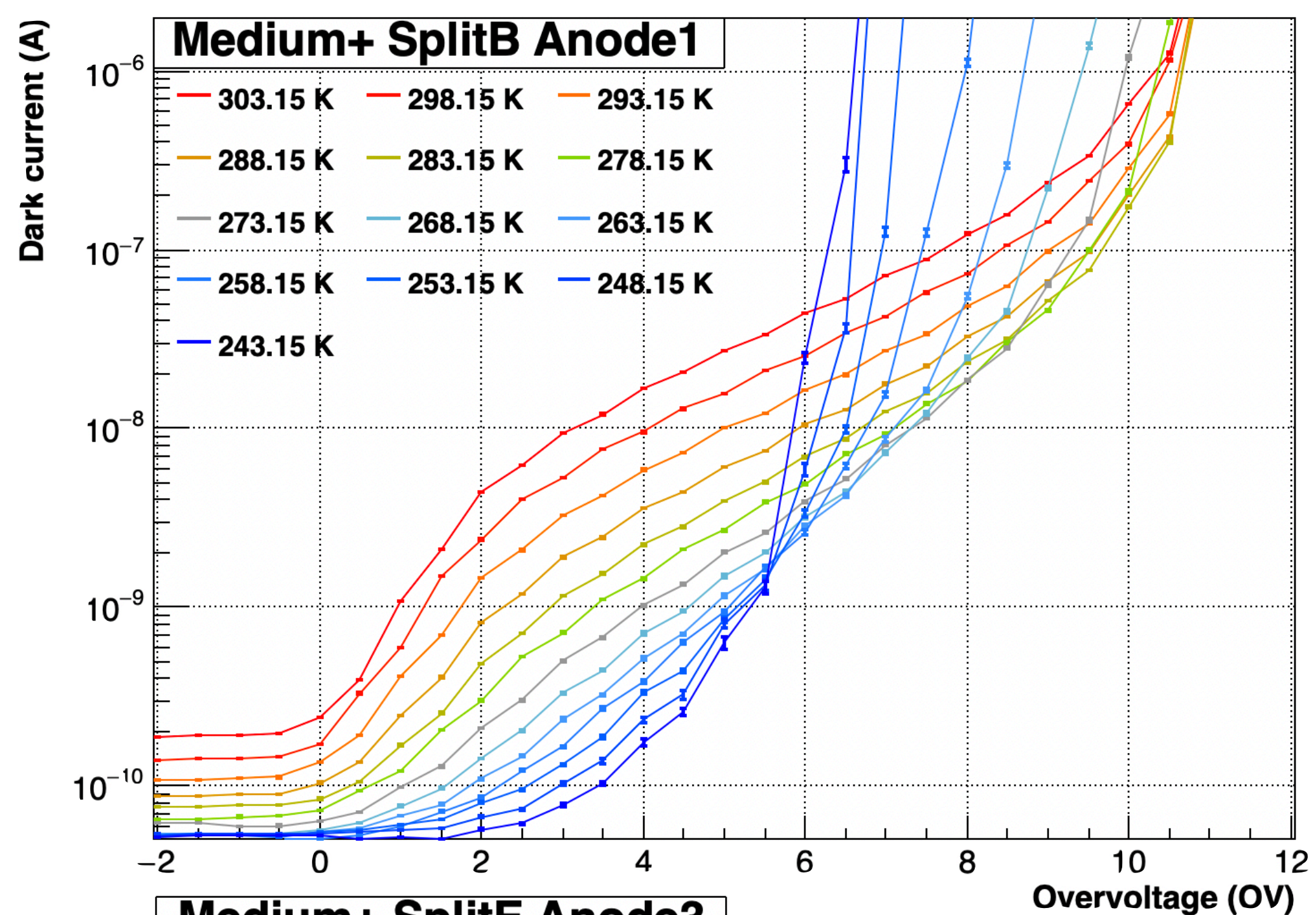
- Sort out V_{BD} accurately
- Check V_{BD} dependence on T



DARK CURRENT CHARACTERIZATION

Using BD results =>
Dark current vs OV





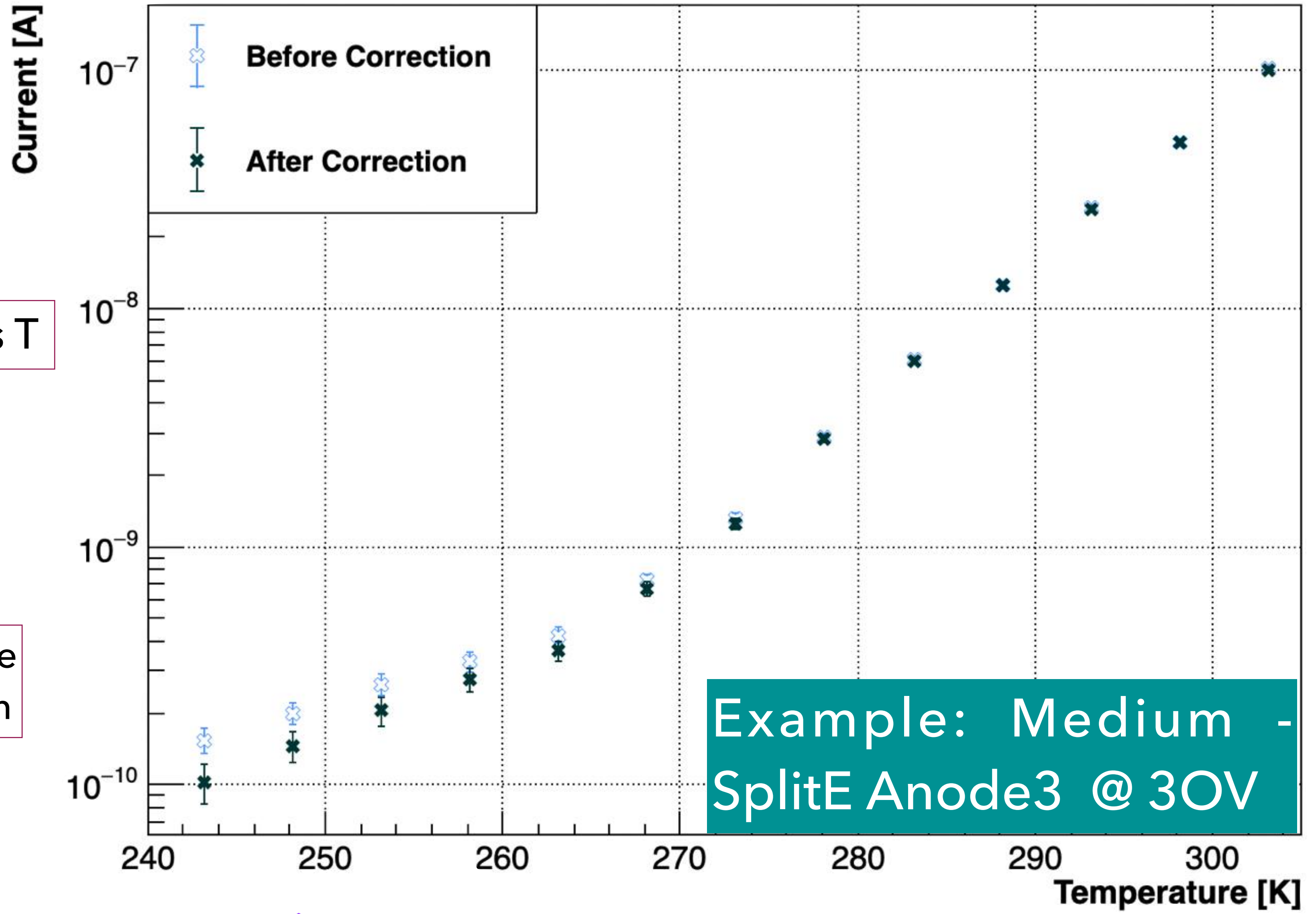
ARRHENIUS PLOT

Arrhenius plot:

Fixing OV (e.g. 3 OV): I vs T

Needed to perform a correction on current

Subtracting the surface current term



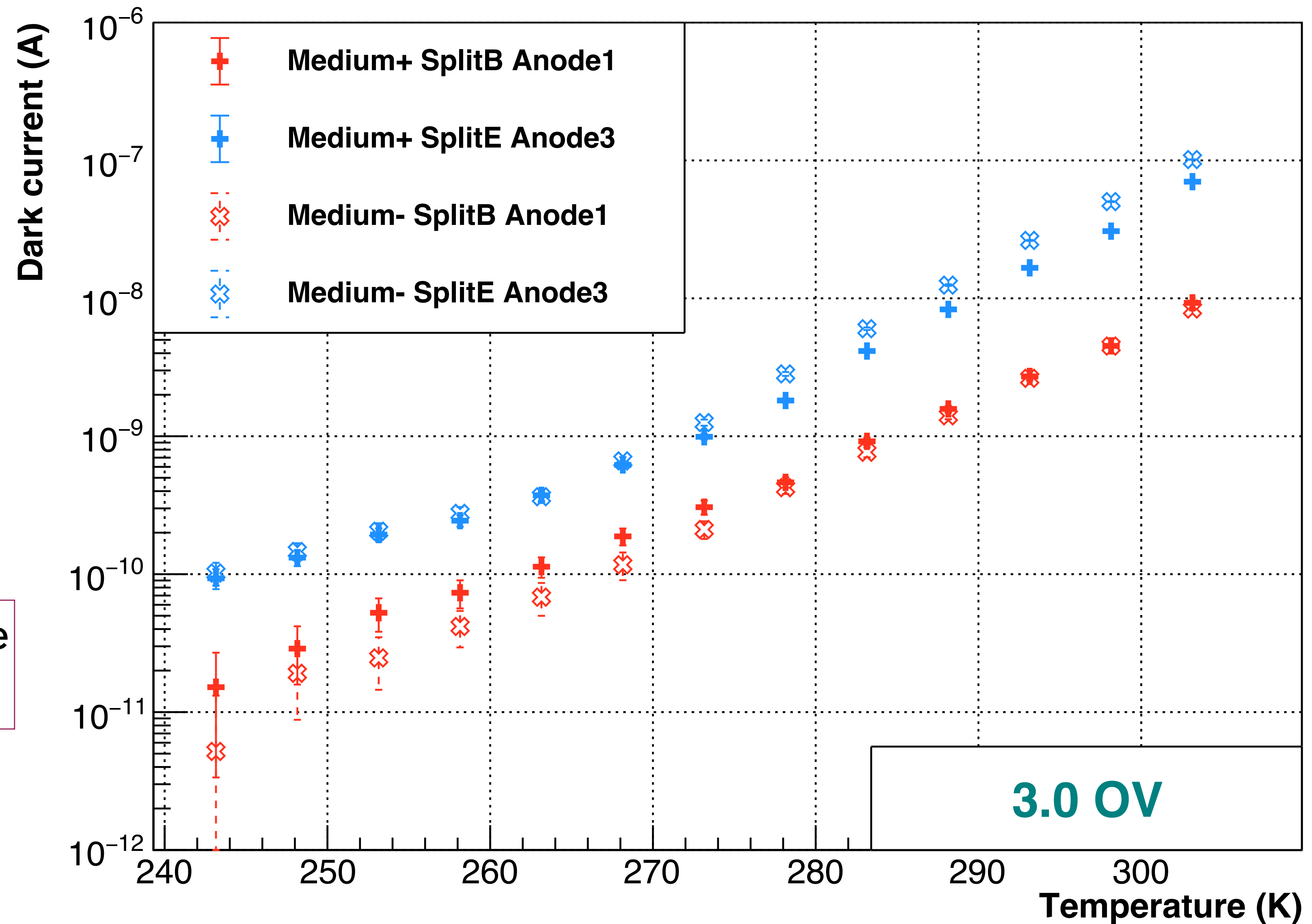
ARRHENIUS PLOT

Arrhenius plot of tested sensors:

Agreement among same split sensors

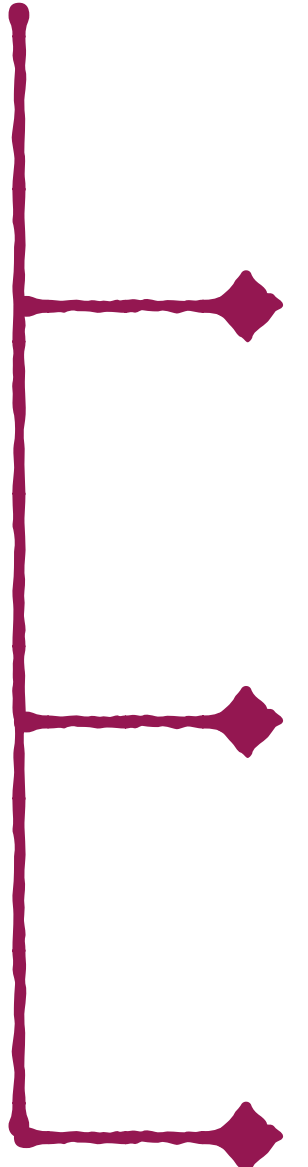
Useful to determine T dependence of current

Useful to determine activation energy of SiPM



ARRHENIUS PLOT

First we determine the T dependence of current

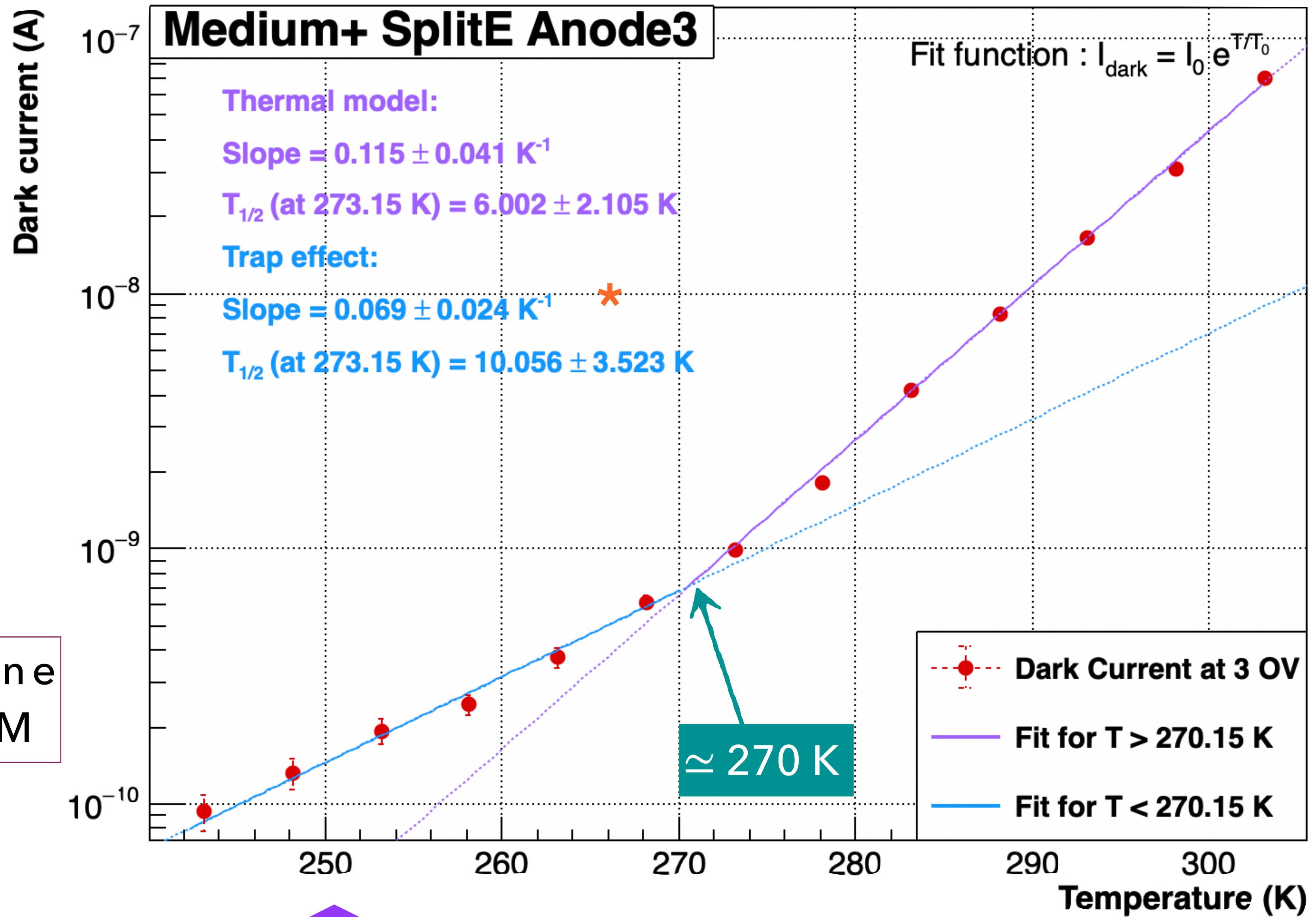


There's a transition around $\simeq -3^{\circ}\text{C}$

$T_{1/2}$ is the T required to halve the current.

Useful to determine activation energy of SiPM

* $T_{1/2} = \frac{\ln(2)}{\text{slope}}$



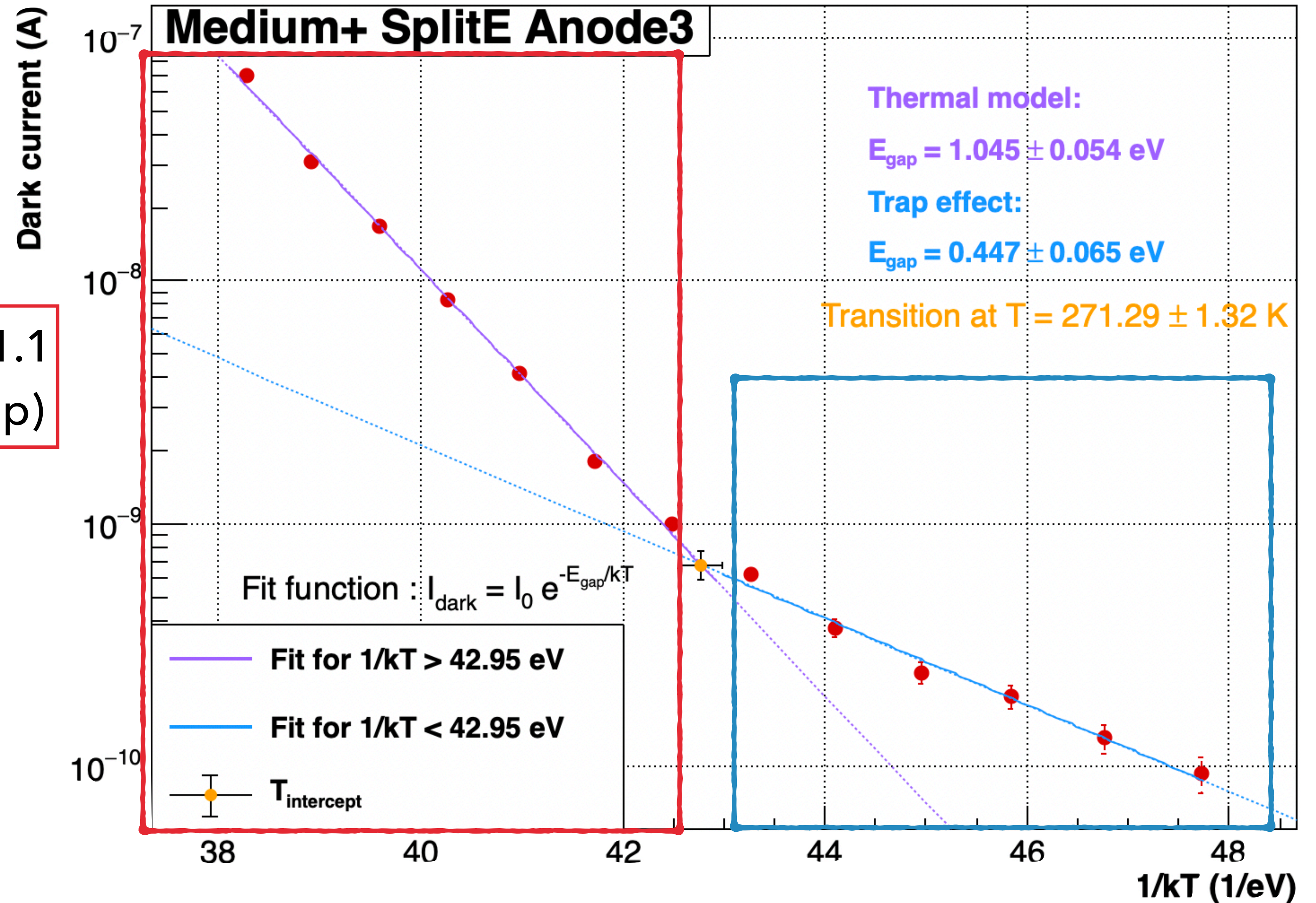
ACTIVATION ENERGY

We then tried to extract the activation energy

At high T: you expect $\simeq 1.1$ eV (silicon energy band-gap)

At low T: you expect less since presence of trap in the band-gap

Transition checked to be around -3°C

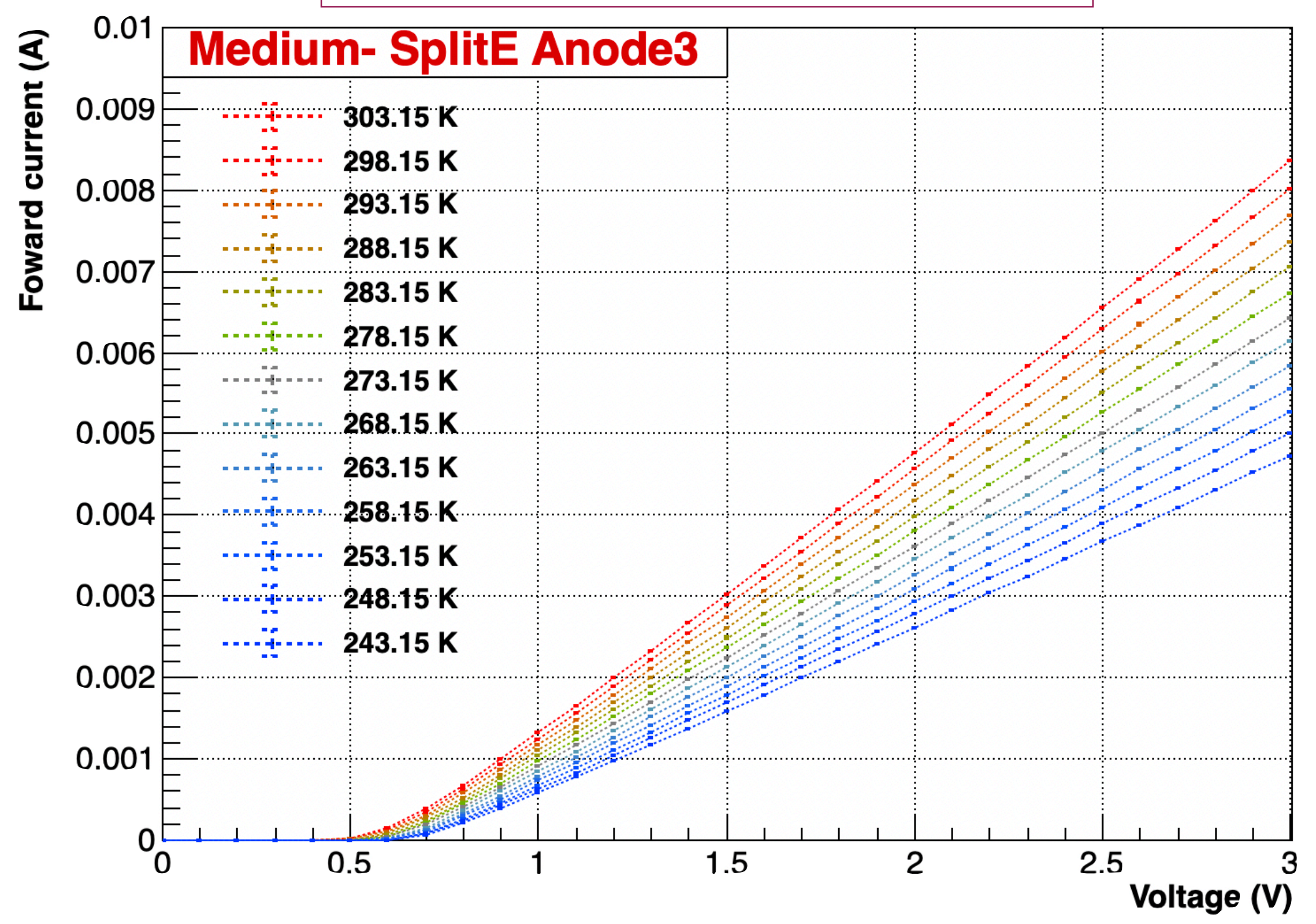


QUENCHING RESISTANCE

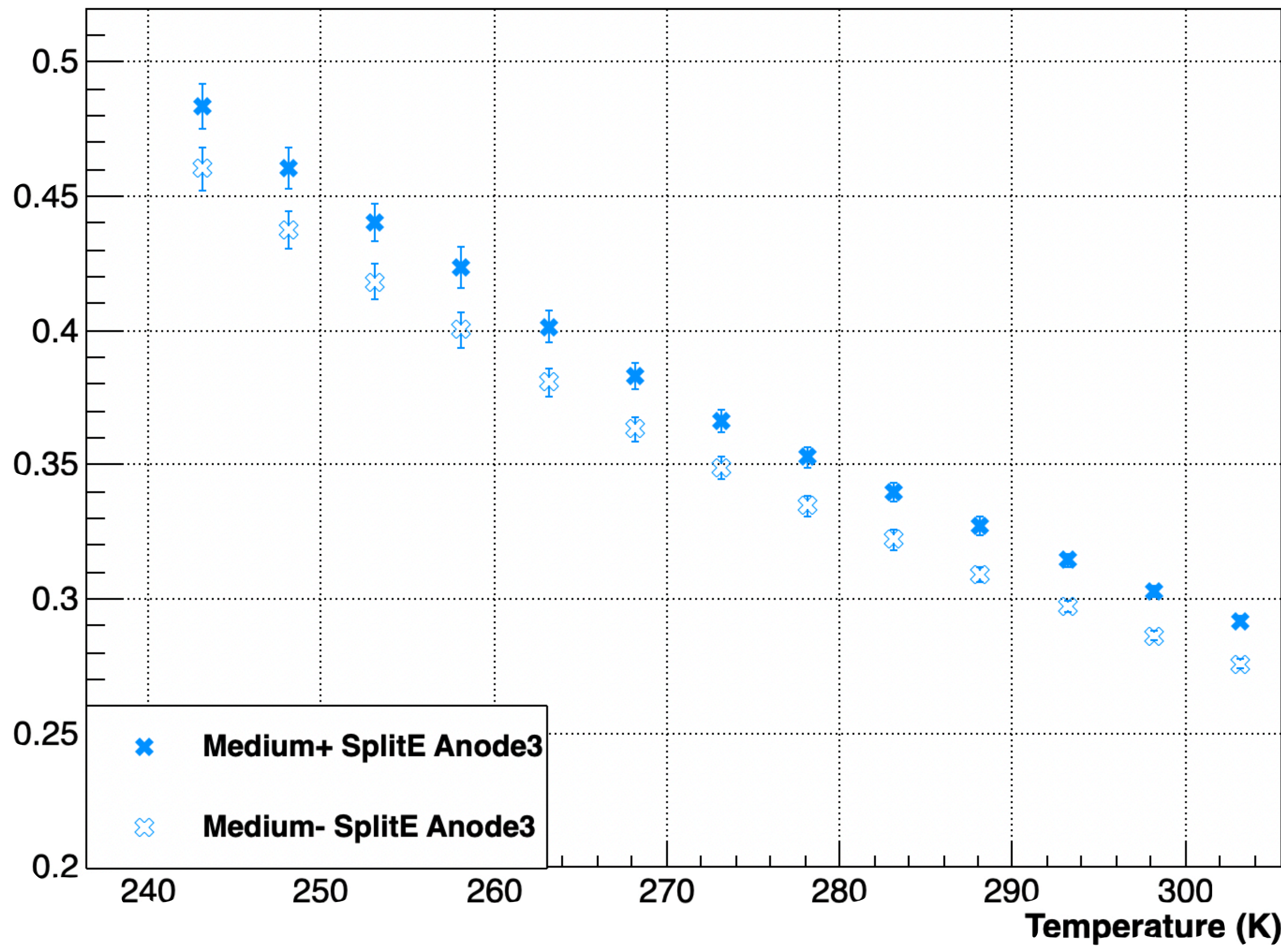
Determine $R_{\text{quenching}}$:

Extracted using Shockley formula: $V = RI + V_T \ln(1 + I/I_S)$

Results found less than $k\Omega$



$R_{\text{quenching}}/N_{\text{cell}}$ ($k\Omega$)



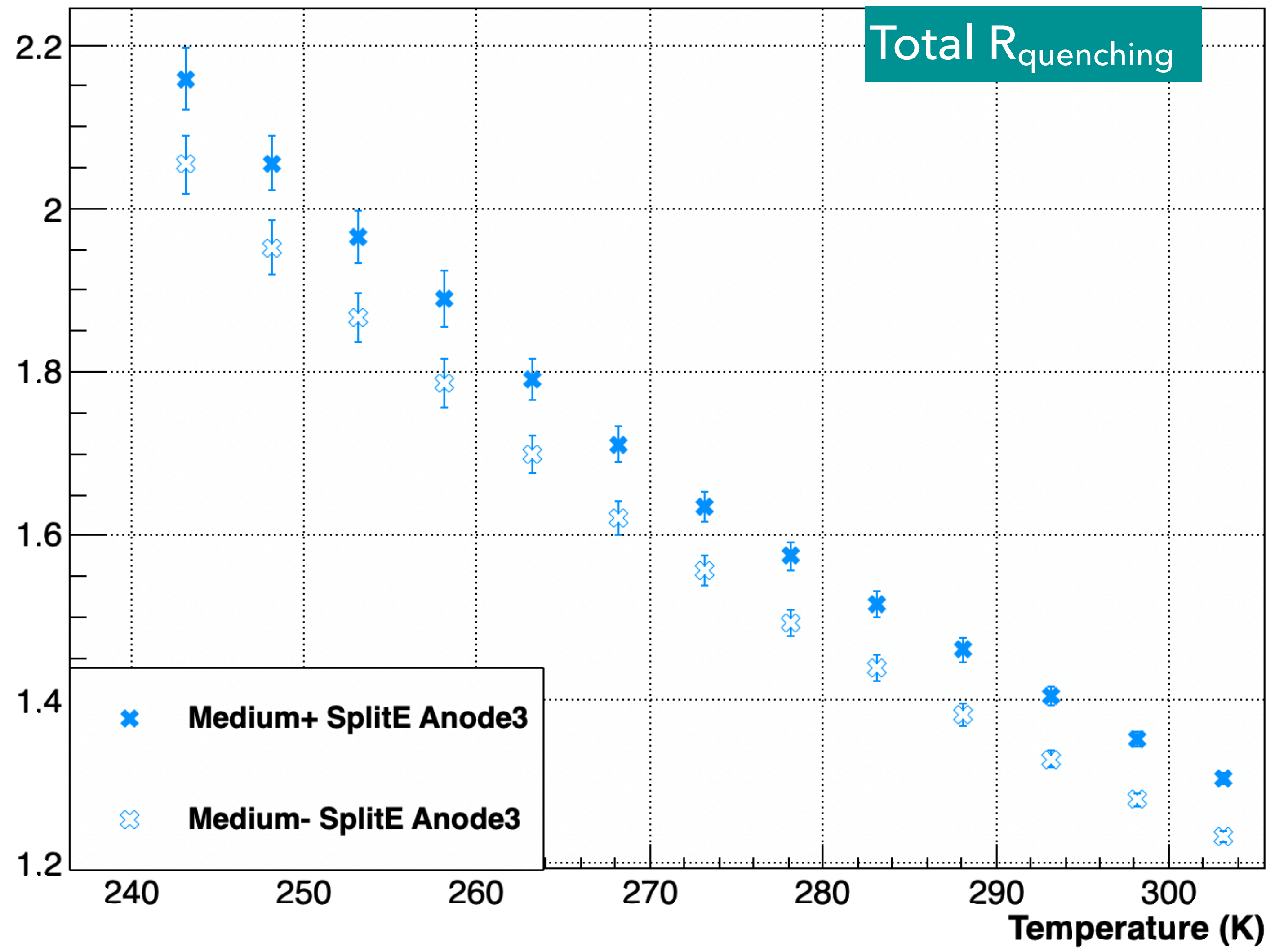
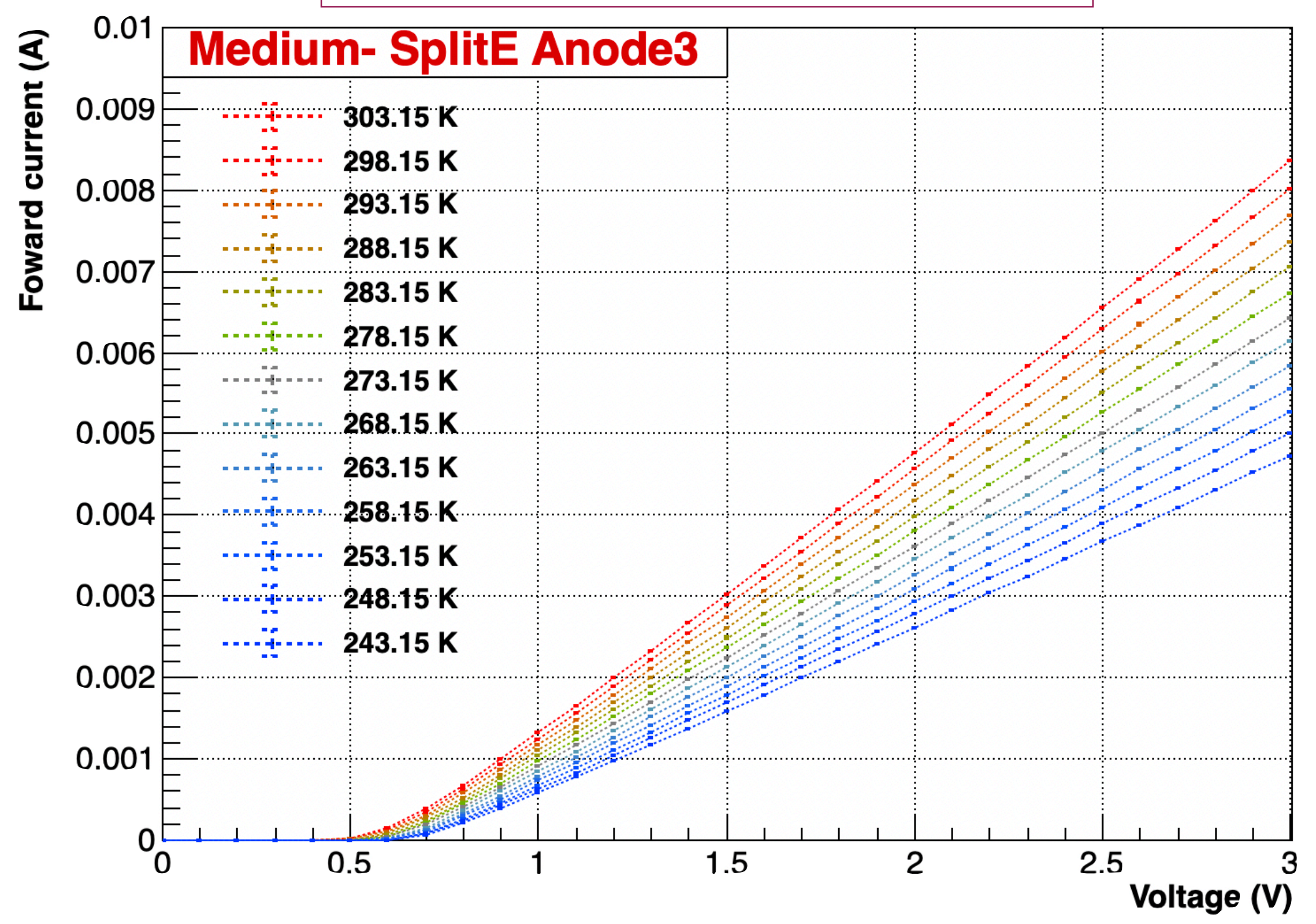
We count 62x72 SPADs => 4464 cells

QUENCHING RESISTANCE

Determine $R_{\text{quenching}}$:

Extracted using Shockley formula: $V = RI + V_T \ln(1 + I/I_S)$

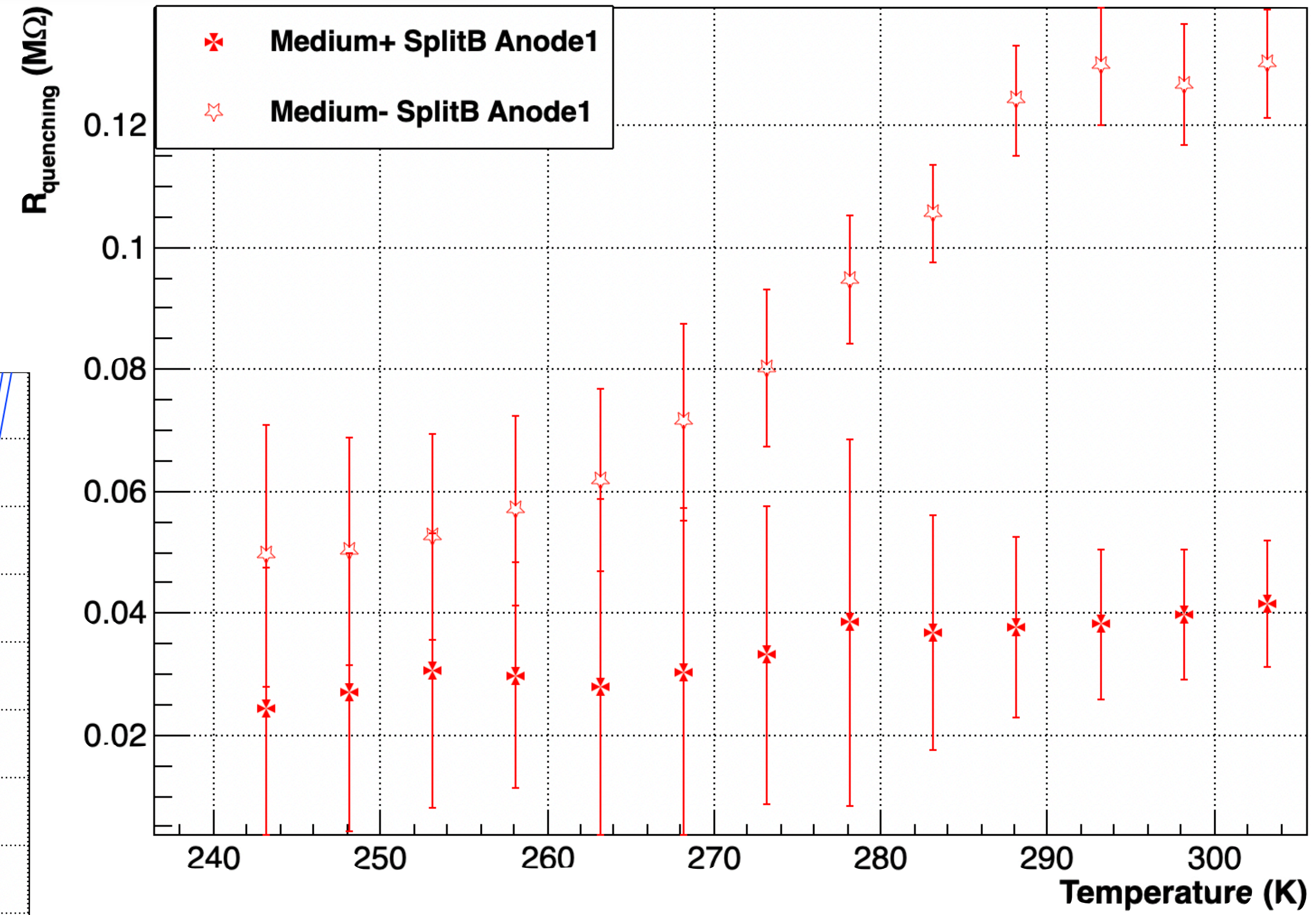
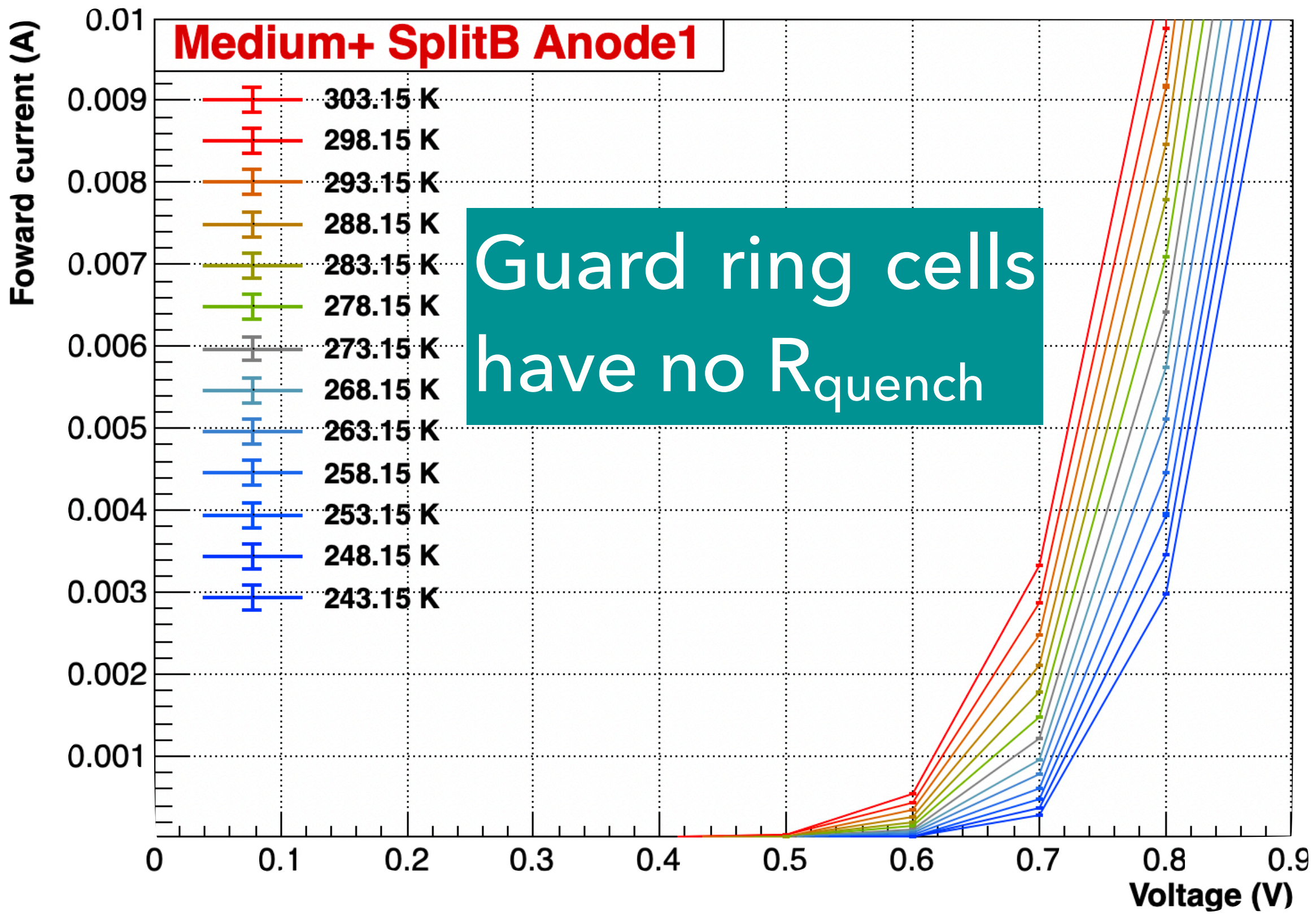
Results found around $M\Omega$



For what concerns Split B guard ring cells have no $R_{\text{quenching}}$

QUENCHING RESISTANCE FOR ANODE 1 AND 2

Let's have a look on Anode 1&2 results of $R_{quenching}$



Fitted again with $V = RI + V_T \ln(1 + I/I_S)$

CONCLUSION:

In conclusion:

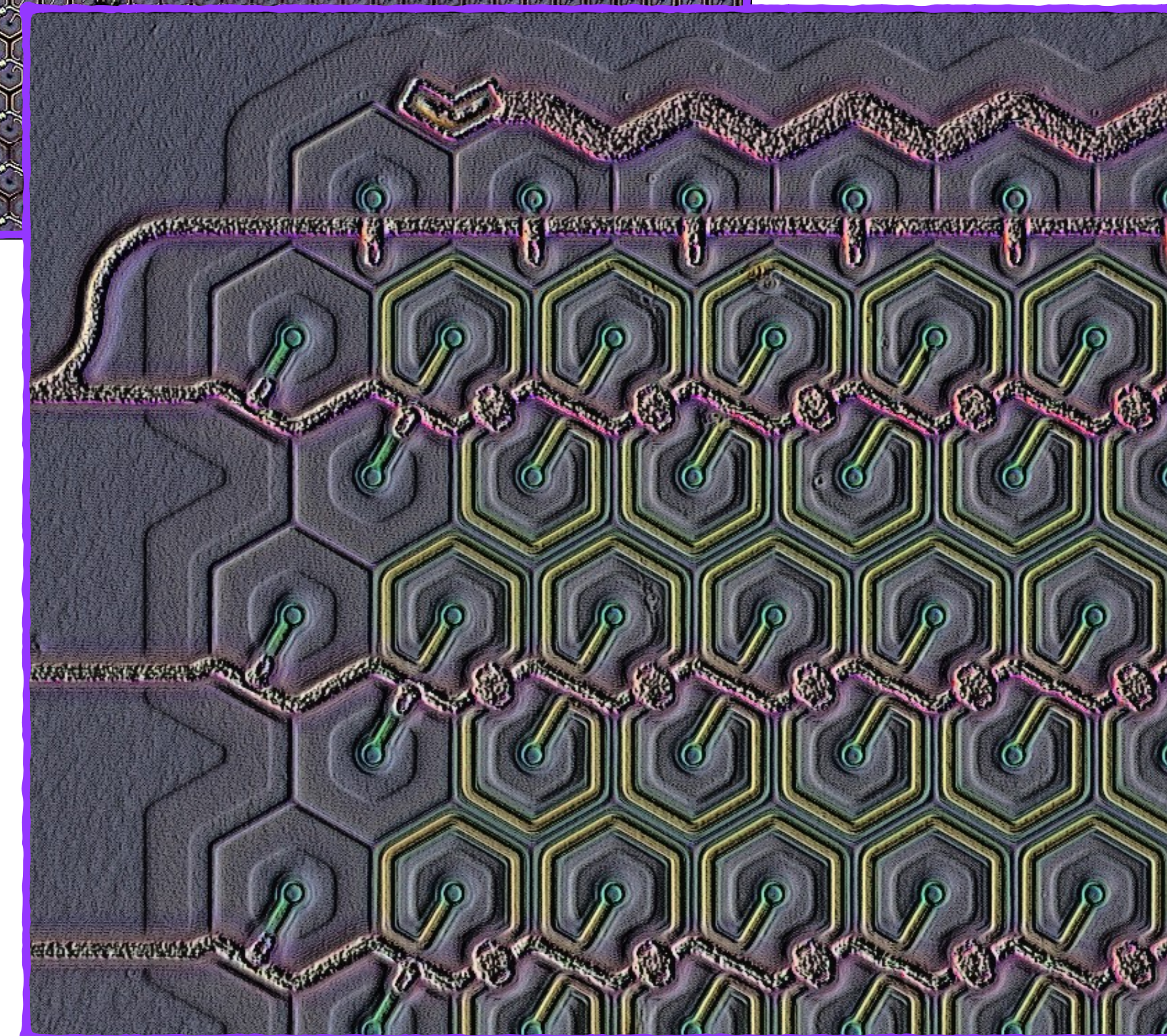
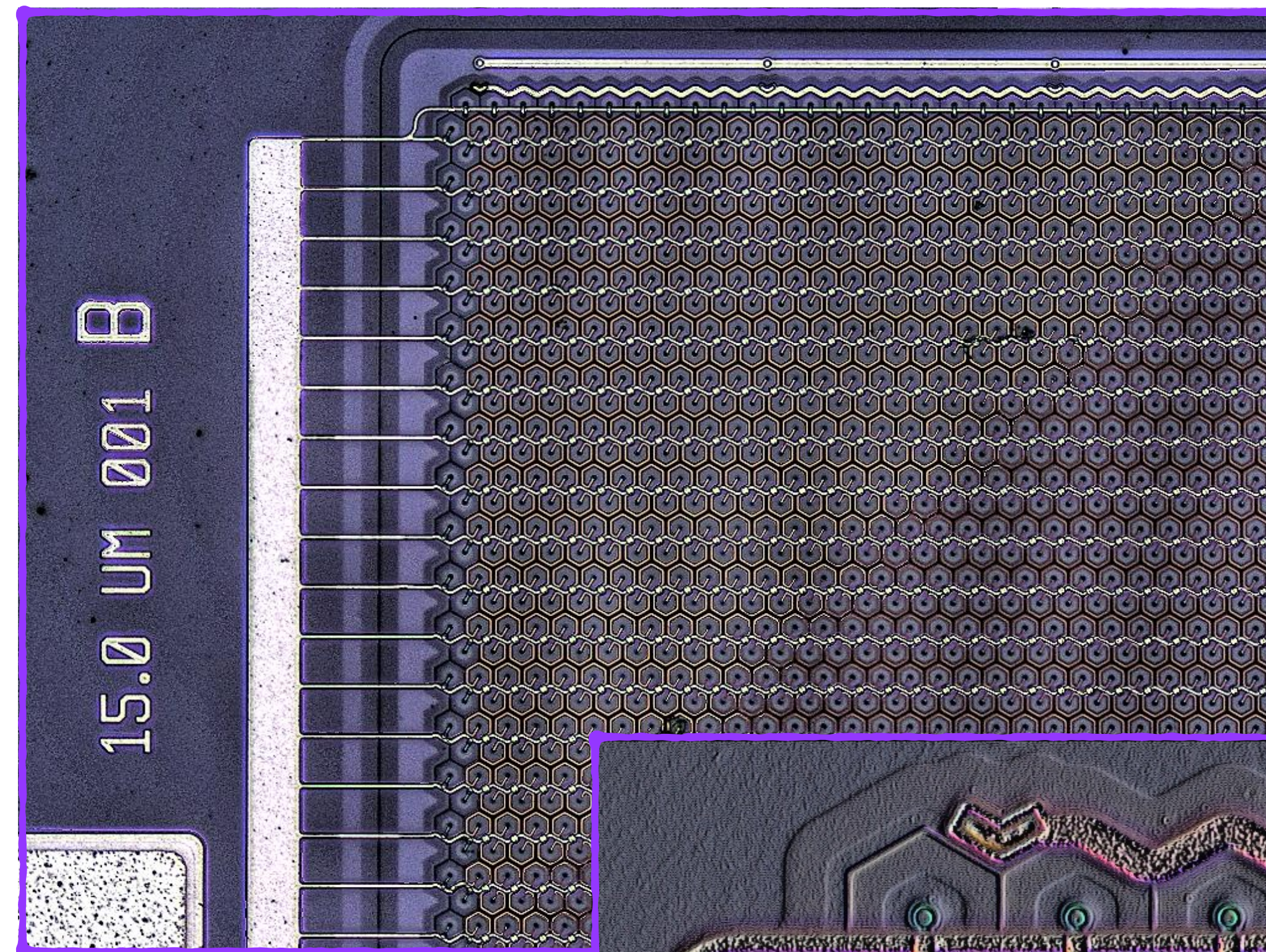
V_{BD} scales as $\simeq 37\text{-}41$ mV/K

Second divergence happens at lower OV when decreasing T

SiPM from same split behaves similarly at fixed OV

$R_{\text{quenching}}$ for split E SiPM is $\simeq M\Omega$, while for split B is not connected

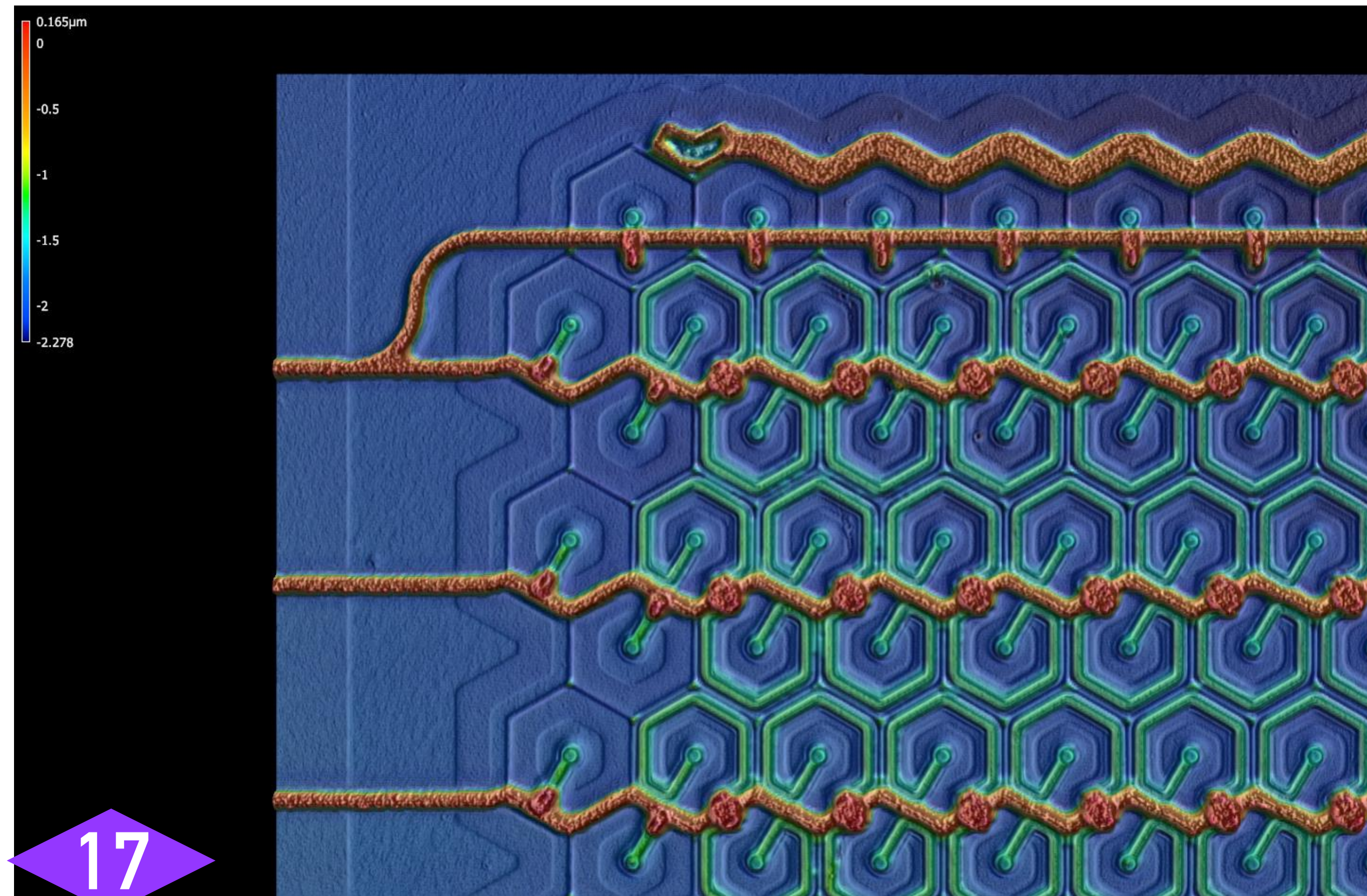
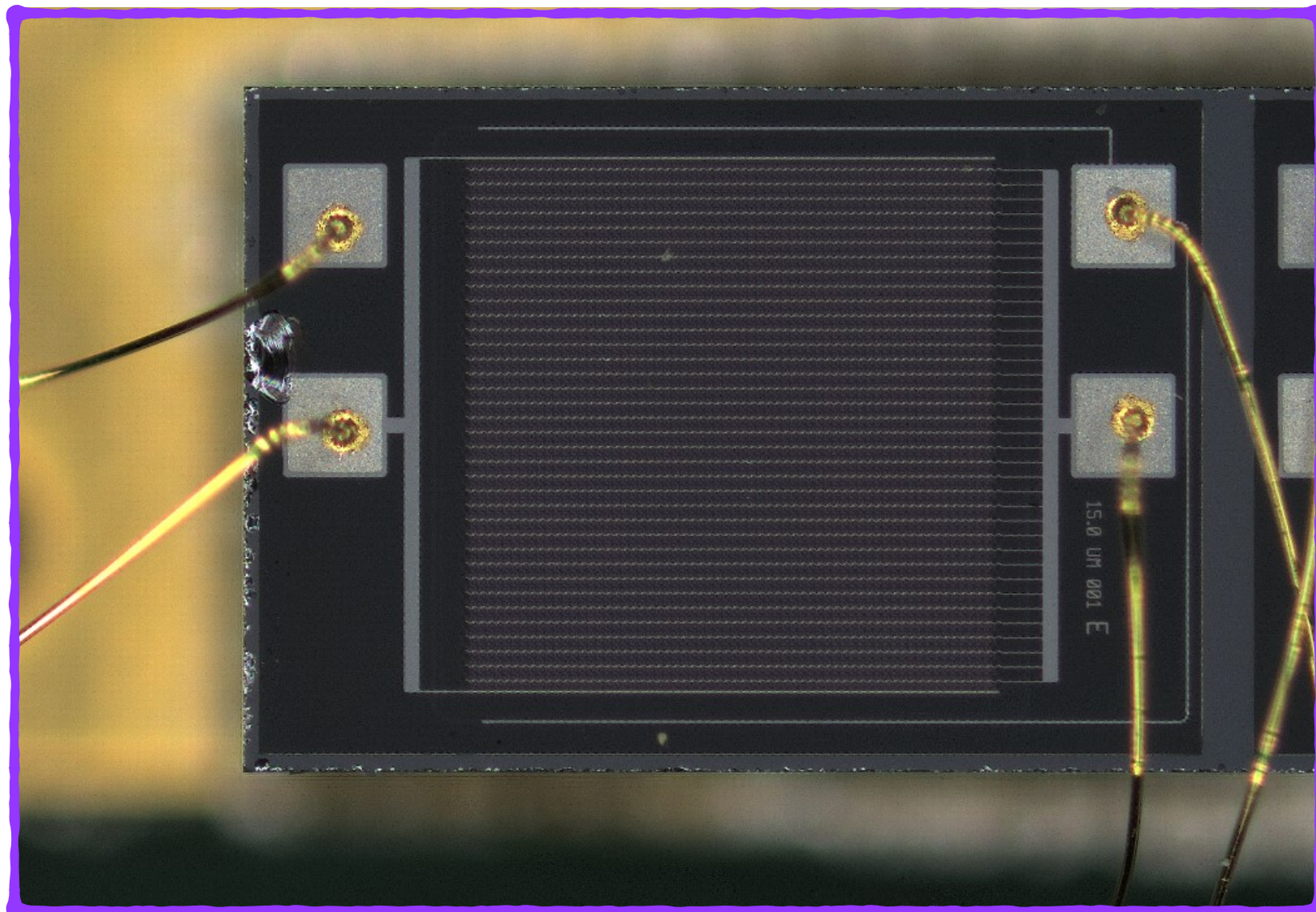
We sort out activation energy and temperature dependence at fixed OV



FUTURE WORK:

We plan to do:

- Extracting V_{BD} for all sensors w/ LED (to be ended)
- Cryogenic measurements
- DCR and signal studies
- Laser and irradiation studies



A microscopic image showing a textured surface with a grid of hexagonal patterns. Each hexagon contains a small circular feature with a central dot. The surface is dark with some lighter, textured lines. The word "END" is overlaid in a white box.

END

**THANK YOU FOR
YOUR ATTENTION**